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AVNER PIERRE BADEHI
Serial No.: 09/725,166
Filed: November 29, 2000
For: **METHODS FOR PRODUCING
PACKAGED INTEGRATED
CIRCUIT DEVICES AND
PACKAGED INTEGRATED
CIRCUIT DEVICES PRODUCED**

Group Art Unit: 2813

Examiner: S. Geyer

CLAIM FOR PRIORITY UNDER 35 U.S.C. § 119

Commissioner for Patents
Washington, D.C. 20231

Sir:

Under the provisions of 35 U.S.C. § 119, filed herewith is a certified copy of Israeli Application No. 133453, filed December 12, 1999, in accordance with the International Convention for the Protection of Industrial Property, 53 Stat. 1748, under which Applicants hereby claim priority, and a verified translation of the priority application.

Respectfully submitted,

Mark S. Bicks
Reg. No. 28,770

ROYLANCE, ABRAMS, BERDO &
GOODMAN, L.L.P.
1300 19th Street, N.W., Suite 600
Washington, D.C. 20036
(202) 659-9076
Dated: Sept 16, 2001



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המסמכים שהופקדו
לכתחילה עם הבקשה
לפטנט לפי הפרטים
הרשמיים בעמוד הראשון
של הנספח.

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יעצת בכירה לרשות הפטנטים

לשימוש הלשכה
For Office Use

133453	מספר : Number
10-12-1993	תאריך : Date
הוקדם/נדחת Ante/Post-dates	

חוק הפטנטים, התשכ"ז -- 1967
PATENTS LAW, 5727-1967

בקשות לפטנט
Application for Patent

C:35699

אני, נ羞 המבקש, מעט -- ולגביו גוף מאונד -- מקום התאגדותו
(Name and address of applicant, and, in case of body corporate-place of incorporation)

SHELLCASE LTD.

P.O. Box 48328
Manhat Technology Park
Jerusalem 96251
(An Israeli company)

שלקיס בע"מ
ת.ד. 48328
גנ טכנולוגיה מלחמה
ירושלים 96251
(חברה ישראלית)

Inventor: Avner Pierre Badehi
(An Israeli citizen)

המציא: אבנר פיר בדייחי
(Azorah Israel)

בעל אמצעה מכח העברית

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of an invention, the title of which is:

שיטת להפקת מעגל משולם א Roz, ומעגל משולב א Roz המיצר על ידי-כך

(בעברית)
(Hebrew)

METHODS FOR PRODUCING PACKAGED INTEGRATED CIRCUIT DEVICES AND
PACKAGES INTEGRATED CIRCUIT DEVICES PRODUCED THEREBY

(באנגלית)
(English)

hereby apply for a patent to be granted to me in respect thereof

מבקש בזאת כי ניתן לי עלייה פטנט		דרישה דין קדימה Priority Claim		
*בקשה חילוקה - Application for Division	*בקשת פטנט מוסף - Application for Patent of Addition	מספר/סיכון Number/Mark	תאריך Date	מדינת האיחוד Convention Country
מבקש פטנט from Application	*לבקשת/לפטנט to Patent/App.			
No. _____ dated _____	No. _____ dated _____	מס.	מס.	מדינת האיחוד Convention Country
*יפוי כת: כלל/מיוחד - רצוף בזאת / עוד יונש P.O.A.: general / individual - attached / to be filed later - filed in case _____ הוגש בעניין _____				
המعن למיסירת הודעות ומסמכים בישראל Address for Service in Israel				
Sanford T. Colb & Co. P.O.B. 2273 Rehovot 76122				
תתיימת המבקש Signature of Applicant				
1999 שנות December 10 בחודש of the year הימים This				

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METHODS FOR PRODUCING PACKAGED INTEGRATED CIRCUIT DEVICES
AND PACKAGES INTEGRATED CIRCUIT DEVICES PRODUCED THEREBY

SHELLCASE LTD.
Inventor: Avner Pierre Badehi
C: 35699

שלקיס בע"מ
המציא: אבנר פיר בדיהי

FIELD OF THE INVENTION

The present invention relates to integrated circuits and similar devices generally and to methods for the manufacture thereof.

BACKGROUND OF THE INVENTION

An essential step in the manufacture of all integrated circuit devices is known as "packaging" and involves mechanical and environmental protection of a silicon chip which is at the heart of the integrated circuit as well as electrical interconnection between predetermined locations on the silicon chip and external electrical terminals.

At present three principal technologies are employed for packaging semiconductors: wire bonding, tape automatic bonding (TAB) and flip chip.

Wire bonding employs heat and ultrasonic energy to weld gold bonding wires between bond pads on the chip and contacts on the package.

Tape automatic bonding (TAB) employs a copper foil tape instead of bonding wire. The copper foil tape is configured for each specific die and package combination and includes a pattern of copper traces suited thereto. The individual leads may be connected individually or as a group to the various bond pads on the chip.

Flip chips are integrated circuit dies which have solder bumps formed on top of the bonding pads, thus allowing the die to be "flipped" circuit side down and directly soldered to a substrate. Wire bonds are not required and considerable savings

in package spacing may be realized.

The above-described technologies each have certain limitations. Both wire bonding and TAB bonding are prone to bad bond formation and subject the die to relatively high temperatures and mechanical pressures. Both wire bond and TAB technologies are problematic from a package size viewpoint, producing integrated circuit devices having a die-to-package area ratio ranging from about 10% to 60%.

The flip-chip does not provide packaging but rather only interconnection. The interconnection encounters problems of uniformity in the solder bumps as well as in thermal expansion mismatching, which limits the use of available substrates to silicon or materials which have thermal expansion characteristics similar to those of silicon.

The patent literature is extremely rich in the area of integrated circuits and methods for the manufacture thereof.

Described in applicant's published PCT Application WO 95/19645 are methods and apparatus for producing integrated circuit devices.

The following U.S. Patents and patent applications of the present inventor are considered to be particularly relevant: 5,716,759; 5,547,906; 5,455,455 and 08/952,019.

SUMMARY OF THE INVENTION

The present invention seeks to provide improved packaged crystalline substrate based devices and methods for producing same.

There is thus provided in accordance with a preferred embodiment of the present invention a crystalline substrate based device including a crystalline substrate having formed thereon a microstructure and at least one packaging layer which is sealed over the microstructure by an adhesive and defines therewith at least one gap between the crystalline substrate and the at least one packaging layer.

There is also provided in accordance with a preferred embodiment of the present invention a chip scale packaged crystalline substrate including:

a substrate having formed thereon a microstructure; and at least one chip scale package which is sealed over the microstructure and defines therewith at least one gap.

There is additionally provided in accordance with a preferred embodiment of the present invention a method of producing a crystalline substrate based device including:

providing a microstructure on a substrate; and adhesively sealing at least one packaging layer over the microstructure and at least partially spaced therefrom, thereby to define a gap between the microstructure and the at least one packaging layer.

Preferably, at least one packaging layer is sealed onto the crystalline substrate using an adhesive, such as epoxy.

In accordance with a preferred embodiment of the

present invention, the crystalline substrate includes silicon, lithium niobate or lithium tantalate.

Preferably, the at least one packaging layer is transparent.

The at least one cavity may include a single cavity or a plurality of cavities.

The microstructure may include a micromechanical structure, a microelectronic structure and/or an optoelectronic structure.

BRIEF DESCRIPTION OF THE DRAWING

Figs. 1A and 1B are pictorial illustrations of a crystalline substrate based device having an internal cavity, constructed and operative in accordance with a preferred embodiment of the present invention;

Figs. 2A, 2B, 2C & 2D are simplified sectional illustrations of various crystalline substrate based devices constructed and operative in accordance with a preferred embodiment of the present invention, corresponding generally to Figs. 1A and 1B;

Fig. 3 is a partially cut-away sectional illustration of a crystalline substrate based device of the type shown in Figs. 1A & 1B;

Figs. 4A, 4B, 4C, 4D & 4E are simplified illustrations of steps in a method for producing a packaging layer for use in crystalline substrate based device in accordance with a preferred embodiment of the present invention;

Figs. 5A, 5B, 5C, 5D, 5E, 5F, 5G, 5H & 5I are simplified illustrations of steps in a method for producing a crystalline substrate based device of the type shown in Figs. 2A & 2C in accordance with a preferred embodiment of the present invention;

Figs. 6A, 6B, 6C, 6D, 6E, 6F, 6G, 6H, 6I, 6J & 6K are simplified illustrations of steps in a method for producing a crystalline substrate based device of the type shown in Fig. 2B in accordance with another preferred embodiment of the present invention;

Figs. 7A, 7B, 7C, 7D, 7E, 7F & 7G are simplified illustrations of steps in a method for producing a crystalline

substrate based device of the type shown in Fig. 2D in accordance with another preferred embodiment of the present invention;

Figs. 8A and 8B are illustrations of apparatus typically employed in the manufacture of a crystalline substrate based devices of the type shown in Figs. 2A & 2C in the manner shown in Figs. 5A - 5I;

Figs. 9A and 9B are illustrations of apparatus typically employed in the manufacture of a crystalline substrate based devices of the type shown in Fig. 2B in the manner shown in Figs. 6A - 6K; and

Figs. 10A and 10B are illustrations of apparatus typically employed in the manufacture of a crystalline substrate based devices of the type shown in Fig. 2D in the manner shown in Figs. 7A - 7G.

DETAILED DESCRIPTION OF PREFERRED EMBODIMENTS

Reference is now made to Figs. 1A and 1B, which together illustrate a preferred embodiment of integrated circuit device constructed and operative in accordance with a preferred embodiment of the present invention. The integrated circuit device includes a relatively thin and compact, environmentally protected and mechanically strengthened integrated circuit package 10 having a multiplicity of electrical contacts 12 plated along the edge surfaces 14 thereof.

Preferably, contacts 12 extend over edge surfaces onto the planar surfaces 16 of the package. This contact arrangement permits both flat surface mounting and edge mounting of package 10 onto a circuit board. It is noted that the integrated circuit package 10 may include one or more of the following elements (not shown): an integrally formed dichroic filter, color filter, antireflective coating, polarizer, optical grating, integrated wave guide and optical coupling bumps.

In accordance with a preferred embodiment of the present invention, the integrated circuit package 10 defines a cavity 18, which is indicated in phantom lines.

Reference is now made to Figs. 2A - 2D, which illustrate four alternative preferred embodiments of integrated circuit devices of the general type shown in Figs. 1A & 1B, constructed and operative in accordance with another preferred embodiment of the present invention. Each of the devices shown in Figs. 2A - 2D includes a relatively thin and compact, environmentally protected and mechanically strengthened integrated circuit package having a multiplicity of electrical contacts plated along

the edge surfaces thereof.

Fig. 2A shows an integrated circuit device including a microlens array 100 formed on a crystalline substrate 102. Underlying the substrate 102 and sealed thereto by epoxy 104 is a packaging layer 106, typically formed of glass, along edges of which are formed electrical contacts 108, typically defining bumps 110. Conductive pads 112 preferably connect substrate 102 to electrical contacts 108.

In accordance with a preferred embodiment of the present invention a packaging layer 114, typically formed of glass, and associated spacer elements 116, are sealed, by means of an adhesive such as epoxy 118, over substrate 102 so as to define a cavity 120 between the microlens array 100 and layer 114.

It is appreciated that packaging layer 114 is preferably transparent and may have formed thereon a dichroic filter and/or anti-reflective coating.

Fig. 2B shows an integrated circuit device including an optoelectronic or electromechanical device 150, such as a chemical sensor, a micromirror array or a miniature mirror array is suspended on a crystalline substrate 152, as by an electrically conductive connector 154. Sealed onto substrate 152 is a packaging layer 156 typically formed of glass, along edges of which are formed electrical contacts 158, typically defining bumps 160. Conductive pads 162 preferably connect substrate 152 to electrical contacts 158.

In accordance with a preferred embodiment of the

present invention a packaging layer 164, typically formed of glass, and associated spacer elements 166, are sealed, by means of an adhesive, such as epoxy 168, over substrate 152 so as to define first and second cavities 170 and 172 between the device 150 and both layer 164 and layer 156.

It is appreciated that packaging layer 164 is preferably transparent and may have formed thereon a dichroic filter and/or anti-reflective coating.

Fig. 2C shows an integrated circuit device including a optoelectronic or electromechanical device 200 formed on a crystalline substrate 202. Underlying the substrate 202 and sealed thereto by epoxy 204 is a packaging layer 206, typically formed of glass, along edges of which are formed electrical contacts 208, typically defining bumps 210. Conductive pads 212 preferably connect substrate 202 to electrical contacts 208.

In accordance with a preferred embodiment of the present invention a packaging layer 214, typically formed of glass, and associated spacer elements 216, are sealed, by means of an adhesive such as epoxy 218, over substrate 202 so as to define a cavity 220 between the device 200 and layer 214.

It is appreciated that packaging layer 214 is preferably transparent and may have formed thereon a dichroic filter and/or anti-reflective coating.

Fig. 2D shows a Surface Acoustic Wave (SAW) device including a SAW propagation surface 250 defined on a crystalline substrate 252, along edges of which are formed electrical contacts 258, typically defining bumps 260. Conductive pads 262 preferably connect substrate 252 to electrical contacts 258.

In accordance with a preferred embodiment of the present invention a packaging layer 264, typically formed of glass, and associated spacer elements 266, are sealed, by means of an adhesive such as epoxy 268, over substrate 252 so as to define a cavity 270 between surface 250 and layer 264.

Reference is now made to Fig. 3, which is a partially cut away illustration of a typical integrated circuit device of the type shown in Figs. 1A - 2D, having a cavity as indicated by reference numeral 280.

Reference is now made to Figs. 4A, 4B, 4C, 4D & 4E, which are simplified illustrations of steps in a method for producing a packaging layer for use in crystalline substrate based device in accordance with a preferred embodiment of the present invention. As seen in Figs. 4A & 4B, a substrate 300, typically formed of glass, is preferably coated with a layer 302 of epoxy based photoresist, typically SU-8 photoresist, commercially available from MicroChem Corp. of Newton, MA, USA.

The photoresist layer 302 is exposed via a mask 304, as shown in Fig. 4C and washed to define spacers 306 shown in Fig. 4D, which are typically of rectangular configuration, as indicated in Fig. 4E. These spacers correspond to spacer elements 116, 166, 216 and 266 in Figs. 2A - 2D respectively.

Reference is now made to Figs. 5A, 5B, 5C, 5D, 5E, 5F, 5G, 5H & 5I, which are simplified illustrations of steps in a method for producing a crystalline substrate based device of the type shown in Figs. 2A & 2C in accordance with a preferred embodiment of the present invention.

As seen in Fig. 5A, a packaging layer 400, typically of the type shown in Figs. 4D and 4E is provided. Adhesive 402 is applied thereto, preferably adjacent and between spacers 406 formed thereon, which correspond to the spacers 306 shown in Figs. 4D & 4E respectively and also correspond to spacer elements 116, 166, 216 and 266 in Figs. 2A - 2D respectively. Adhesive 402 is preferably a high temperature epoxy, such as EPO-TEK 353ND, commercially available from Epoxy Technology Inc. of Billerica, MA, USA.

As shown in Fig. 5B, the packaging layer 400, thus prepared, is adhered to a crystalline substrate 404, typically having at least one metal layer thereon and having mounted thereon optomechanical or optoelectronic devices of the types described hereinabove with reference to Figs. 2A & 2C. As seen clearly, a cavity 405 is defined between the packaging layer 400 and the substrate 404, in accordance with a preferred embodiment of the present invention.

The crystalline substrate 404 is preferably lapped, as shown in Fig. 5C and etched, as shown in Fig. 5D, to define separate substrates 407. Following etching, the substrates 407 are adhered via an epoxy layer 408 to an underlying packaging layer 410, as shown in Fig. 5E.

As seen in Fig. 5F, the packaging layer 410 and epoxy layer 408 are mechanically notched and thereafter electrical contacts 412 and typically bumps 414 are formed thereon, as seen in Fig. 5G. The resulting assembly is diced as shown in Fig. 5H to yield a plurality of packaged integrated circuit devices, as seen in Fig. 5I.

It is appreciated that here and throughout all of the examples described herein, the crystalline substrate may be any suitable crystalline substrate and may comprise, for example, silicon, lithium niobate or lithium tantalate.

The manufacturing techniques described hereinabove and hereinbelow may but need not necessarily include techniques described in any of the following U.S. Patents and patent applications of the present inventor/assignee, the disclosure of which is hereby incorporated by reference: 5,716,759; 5,547,906; 5,455,455 and 08/952,019.

Reference is now made to Figs. 6A, 6B, 6C, 6D, 6E, 6F, 6G, 6H, 6I, 6J & 6K, which are simplified illustrations of steps in a method for producing a crystalline substrate based device of the type shown in Fig. 2B in accordance with another preferred embodiment of the present invention.

As seen in Fig. 6A, mounted on a substrate 500, typically formed of Pyrex are a plurality of crystalline substrates 502 onto which are formed pads 504 and onto which are suspended, as by electrically conductive connectors 506, optoelectronic or electromechanical devices 508, such as chemical sensors, micro-mirror arrays or a miniature mirror arrays, which may correspond to devices 150 of the type shown in Fig. 2B.

As shown in Fig. 6B, a packaging layer 510, typically of the type shown in Figs. 4D and 4E, is provided having adhesive 512 applied thereto, preferably adjacent and between spacers 516 formed thereon, which correspond to the spacers 306 shown in Figs. 4D & 4E respectively and also correspond to spacer ele-

ments 116, 166, 216 and 266 in Figs. 2A - 2D respectively. Adhesive 512 is preferably a high temperature epoxy, such as EPO-TEK 353ND, commercially available from Epoxy Technology Inc. of Billerica, MA, USA.

As seen in Fig. 6C, the packaging layer 510, thus prepared, is adhered to crystalline substrates 502, typically adjacent pads 504. As seen clearly, a cavity 513 is defined between the packaging layer 510 and the substrates 502, and another cavity 514 is defined between substrates 502, substrate 500 and electromechanical devices 508 in accordance with a preferred embodiment of the present invention.

The substrate 500 and crystalline substrates 502 are preferably notched, as shown in Fig. 6D and etched, as shown in Fig. 6E, to define volumes 515 in crystalline substrates 502 which are preferably filled with epoxy 517, as shown in Fig. 6F.

As seen in Fig. 6G, the substrate 500, the epoxy 516 and the adhesive 512 are then mechanically notched to form a notch 501, and thereafter electrical contacts 519 are formed thereon, as by sputtering, as shown in Fig. 6H. Bumps 518 are formed thereon, as seen in Fig. 6I, preferably together with a NiAu coating. The resulting assembly is diced as shown in Fig. 6J to yield a plurality of packaged integrated circuit devices, as seen in Fig. 6K.

Reference is now made to Figs. 7A, 7B, 7C, 7D, 7E, 7F & 7G, which are simplified illustrations of steps in a method for producing a crystalline substrate based device of the type shown in Fig. 2D in accordance with another preferred embodiment of the present invention.

As seen in Fig. 7A, a packaging layer 600, typically of the type shown in Figs. 4D and 4E is provided. Adhesive 602 is applied thereto, preferably adjacent and between spacers 606 formed thereon, which correspond to the spacers 306 shown in Figs. 4D & 4E respectively and also correspond to spacer elements 116, 166, 216 and 266 in Figs. 2A - 2D respectively. Adhesive 602 is preferably a high temperature epoxy, such as EPO-TEK 353ND, commercially available from Epoxy Technology Inc. of Billerica, MA, USA.

As shown in Fig. 7B, the packaging layer 600, thus prepared, is adhered to a crystalline substrate 604, typically having at least one metal layer thereon and having defined thereon a SAW propagation layer 609 as described hereinabove with reference to Fig. 2D. As seen clearly, a cavity 607 is defined between the packaging layer 600 and the SAW propagation layer 609, in accordance with a preferred embodiment of the present invention.

The crystalline substrate 604 can be lapped, as shown in Fig. 7C and notched partially into the adhesive 602, as shown in Fig. 7D, to define separate substrates 608. Following etching, electrical contacts 610 and typically bumps 614 are formed thereon, as seen in Fig. 7E. The resulting assembly is diced as shown in Fig. 7F to yield a plurality of packaged SAW devices, as seen in Fig. 7G.

Reference is now made to Figs. 8A and 8B, which are illustrations of apparatus employed in the manufacture of a crystalline substrate based devices of the type shown in Figs. 2A

& 2C in the manner shown in Figs. 5A - 5I. As seen in Figs. 8A and 8B, a conventional wafer fabrication facility 680 provides complete wafers 681, of the type shown in Fig. 5A. Individual wafers 682 are bonded on their active surfaces to protective layers 683 as shown in Figs. 5A & 5B, by bonding apparatus 685, preferably having facilities for rotation of the wafer 682, the layer 683 and the epoxy so as to obtain even distribution of the epoxy.

The bonded wafer 686 is thinned (Fig. 5C) at its non-active surface as by grinding apparatus 684, such as Model 32BTGW using 12.5A abrasive 687, which is commercially available from Speedfam Machines Co. Ltd. of England.

The wafer is then etched (Fig. 5D) at its non-active surface, preferably by photolithography, such as by using conventional spin-coated photoresist, which is commercially available from Hoechst, under the brand designation AZ 4562, using a mask exposure machine 692 for the exposure of light sensitive photoresist the through mask 691 and later etching the silicon in a bath 693 using solution 699.

The etched wafer 1000 is bonded (Fig. 5E) on the non-active side to protective layer 686 by bonding apparatus 694, which may be essentially the same as apparatus 685, to produce a doubly bonded wafer sandwich.

Notching apparatus 695 partially cuts the bonded wafer sandwich of Fig. 5E to the configuration shown in Fig. 5F.

The notched wafer 1002 is then preferably subjected to anti-corrosion treatment in a bath 696, containing a chromating solution 698, such as described in any of the following U.S.

Patents: 2,507,956; 2,851,385 and 2,796,370, the disclosure of which is hereby incorporated by reference.

Conductive layer deposition apparatus 700, which operates by vacuum deposition techniques, such as a Model 903M sputtering machine manufactured by Material Research Corporation of the U.S.A., is employed to produce a conductive layer on one or more surfaces of each die of the wafer as shown in Fig. 5G.

Configuration of contact strips, as shown in Fig. 5G, is carried out preferably by using conventional electro-deposited photoresist 701, which is commercially available from DuPont under the brand name Primecoat or from Shipley, under the brand name Eagle. The photoresist 701 is applied to the wafers 707 in a photoresist bath assembly 702 which is commercially available from DuPont or Shipley.

The photoresist 703 is preferably light configured by a UV exposure system 704, which may be identical to system 692, using a mask 705 to define suitable etching patterns. The photoresist is then developed in a development bath 706, and then etched in a metal etch solution 708 located in an etching bath 710, thus providing a conductor configuration such as that shown in Fig. 5G.

The exposed conductive strips shown in Fig. 5G are then plated, preferably by electroless plating apparatus 712, which is commercially available from Okuno of Japan.

The wafer is then diced (Fig. 5H) into individual pre-packaged integrated circuit devices. Preferably the dicing blade 714 should be a diamond resinoid blade of thickness 4 - 12 mils.

The resulting dies appear as illustrated generally in Fig. 5I.

Reference is now made to Figs. 9A and 9B, which are illustrations apparatus employed in the manufacture of a crystalline substrate based devices of the type shown in Fig. 2B in the manner shown in Figs. 6A - 6K. As seen in Figs. 9A and 9B, a wafer fabrication facility 780 provides complete wafers 781, of the type shown in Fig. 6A mounted onto a substrate, such as a Pyrex substrate 782. Individual wafers 781 are bonded on their active surfaces to protective layers 783 as shown in Figs. 6B & 6C, by bonding apparatus 784, preferably having facilities for rotation of the wafer 781, the layer 783 and the epoxy so as to obtain even distribution of the epoxy.

Notching apparatus 794 partially cuts the bonded wafer sandwich 793 of Fig. 6C to the configuration shown in Fig. 6D. The notched wafer 796 is then etched in a silicon etching solution 798 in a bath 1010. The etched voids 1012 in wafer 1014 are filled with epoxy 1016, using a dispenser 1018 to fill the voids 1012, to obtain epoxy filled voids 1020. The wafer 1022 is notched again using apparatus 1024 through the epoxy filled trenches 1020.

The notched wafer 1028 is then preferably subjected to anti-corrosion treatment in a bath 1030, containing a chromating solution 1032, such as described in any of the following U.S. Patents: 2,507,956; 2,851,385 and 2,796,370, the disclosure of which is hereby incorporated by reference.

Conductive layer deposition apparatus 800, which operates by vacuum deposition techniques, such as a Model 903M sputtering machine manufactured by Material Research Corporation of

the U.S.A., is employed to produce a conductive layer on one or more surfaces of each die of the wafer as shown in Fig. 6G.

Configuration of contact strips, as shown in Fig. 6E, is carried out preferably by using conventional electro-deposited photoresist 801, which is commercially available from DuPont under the brand name Primecoat or from Shipley, under the brand name Eagle. The photoresist is applied to the wafers 803 in a photoresist bath assembly 802 which is commercially available from DuPont or Shipley.

The photoresist 807 is preferably light configured by a UV exposure system 804, which may be identical to system 685, using a mask 805 to define suitable etching patterns. The photoresist is then developed in a development bath 806, and then etched in a metal etch solution 808 located in an etching bath 810, thus providing a conductor configuration such as that shown in Fig. 1B.

The exposed conductive strips shown in Fig. 6G are then plated, preferably by electroless plating apparatus 812, which is commercially available from Okuno of Japan.

The wafer is then diced (Fig. 6H) into individual pre-packaged integrated circuit devices. Preferably the dicing blade 814 should be a diamond resinoid blade of thickness 4 - 12 mils. The resulting dies appear as illustrated generally in Fig. 6K.

Reference is now made to Figs. 10A and 10B, which are illustrations apparatus employed in the manufacture of a crystal-line substrate based device of the type shown in Fig. 2D in the manner shown in Figs. 7A - 7G. As seen in Figs. 10A and 10B, a

conventional wafer fabrication facility 880 provides complete wafers 881, of the type shown in Fig. 7A. Individual wafers 881 are bonded on their active surfaces to protective layers 883 as shown in Figs. 7A & 7B, by bonding apparatus 882, preferably having facilities for rotation of the wafer 881, the layer 883 and the epoxy so as to obtain even distribution of the epoxy.

Notching apparatus 894 partially cuts the wafer 883 of Fig. 7E to the configuration shown in Fig. 7F.

The notched wafer 884 is then preferably subjected to anti-corrosion treatment in a bath 896, containing a chromating solution 898, such as described in any of the following U.S. Patents: 2,507,956; 2,851,385 and 2,796,370, the disclosure of which is hereby incorporated by reference.

Conductive layer deposition apparatus 900, which operates by vacuum deposition techniques, such as a Model 903M sputtering machine manufactured by Material Research Corporation of the U.S.A., is employed to produce a conductive layer on one or more surfaces of each die of the wafer as shown in Fig. 7G.

Configuration of contact strips, as shown in Fig. 7E, is carried out preferably by using conventional electro-deposited photoresist 901, which is commercially available from DuPont under the brand name Primecoat or from Shipley, under the brand name Eagle. The photoresist 901 is applied to the wafers 903 in a photoresist bath assembly 902 which is commercially available from DuPont or Shipley.

The photoresist 920 is preferably light configured by a UV exposure system 904 using a mask 905 to define suitable etching patterns. The photoresist is then developed in a develop-

ment bath 906, and then etched in a metal etch solution 908 located in an etching bath 910, thus providing a conductor configuration such as that shown in Fig. 1B.

The exposed conductive strips shown in Fig. 7G are then plated, preferably by electroless plating apparatus 912, which is commercially available from Okuno of Japan.

The wafer 913 is then diced (Fig. 5H) into individual pre-packaged integrated circuit devices. Preferably the dicing blade 914 should be a diamond resinoid blade of thickness 4 - 12 mils. The resulting dies appear as illustrated generally in Fig. 7G.

It will be appreciated by persons skilled in the art that the present invention is not limited by what has been particularly shown and described hereinabove. Rather the scope of the present invention includes both combinations and subcombinations of various features described hereinabove as well as modifications and variations thereof which would occur to a person of skill in the art upon reading the foregoing description and referring to the drawings and which are not in the prior art.

C L A I M S

1. A crystalline substrate based device comprising:
a crystalline substrate having formed thereon a micro-
structure; and
at least one packaging layer which is sealed over said
microstructure by means of an adhesive and defines therewith at
least one gap between said crystalline substrate and said at
least one packaging layer.
2. A crystalline substrate based device according to
claim 1 and wherein said at least one packaging layer is sealed
onto said crystalline substrate using an adhesive.
3. A crystalline substrate based device according to
claim 2 and wherein said adhesive comprises epoxy.
4. A crystalline substrate based device according to
claim 1 and wherein said crystalline substrate comprises silicon.
5. A crystalline substrate based device according to
claim 1 and wherein said crystalline substrate comprises lithium
niobate.
6. A crystalline substrate based device according to
claim 1 and wherein said at least one packaging layer is trans-
parent.
7. A crystalline substrate based device according to
claim 1 and wherein said at least one cavity comprises a pluraliti-
ty of cavities.

8. A crystalline substrate based device according to claim 1 and wherein said microstructure comprises a micromechanical structure.

9. A crystalline substrate based device according to claim 1 and wherein said microstructure comprises a microelectronic structure.

10. A crystalline substrate based device according to claim 1 and wherein said microstructure comprises a optoelectronic structure.

11. A chip scale packaged crystalline substrate comprising: a substrate having formed thereon a microstructure; and at least one chip scale package which is sealed over said microstructure and defines therewith at least one gap.

12. A chip scale packaged crystalline substrate according to claim 11 and wherein said at least one package is sealed onto said substrate using an adhesive.

13. A chip scale packaged crystalline substrate based device according to claim 12 and wherein said adhesive comprises epoxy.

14. A chip scale packaged crystalline substrate according to claim 11 and wherein said substrate comprises silicon.

15. A chip scale packaged crystalline substrate according to claim 11 and wherein said substrate comprises lithium niobate.

16. A chip scale packaged crystalline substrate according to claim 11 and wherein said at least one package is at least partially transparent.

17. A chip scale packaged crystalline substrate according to claim 11 and wherein said at least one cavity comprises a plurality of cavities.

18. A chip scale packaged crystalline substrate according to claim 11 and wherein said microstructure comprises a micromechanical structure.

19. A chip scale packaged crystalline substrate according to claim 11 and wherein said microstructure comprises a microelectronic structure.

20. A chip scale packaged crystalline substrate according to claim 1 and wherein said microstructure comprises a optoelectronic structure.

21. A method of producing a crystalline substrate based device comprising:

providing a microstructure on a substrate; and
adhesively sealing at least one packaging layer over
said microstructure and at least partially spaced therefrom,
thereby to define a gap between said microstructure and said at
least one packaging layer.

22. A method of produce a crystalline substrate based device according to claim 21 and wherein said at least one packaging layer is sealed onto said crystalline substrate using an

adhesive.

23. A method of produce a crystalline substrate based device according to claim 22 and wherein said adhesive comprises Epoxy.

24. A method of produce a crystalline substrate based device according to claim 21 and wherein said crystalline substrate comprises silicon.

25. A method of produce a crystalline substrate based device according to claim 21 and wherein said crystalline substrate comprises lithium niobate.

26. A method of produce a crystalline substrate based device according to claim 21 and wherein said at least one packaging layer is transparent.

27. A method of produce a crystalline substrate based device according to claim 21 and wherein said at least one cavity comprises a plurality of cavities.

28. A method of produce a crystalline substrate based device according to claim 21 and wherein said microstructure comprises a micromechanical structure.

29. A method of produce a crystalline substrate based device according to claim 21 and wherein said microstructure comprises a microelectronic structure.

30. A method of produce a crystalline substrate based

device according to claim 21 and wherein said microstructure comprises a optoelectronic structure.

31. A crystalline substrate based device according to claim 1 and wherein said crystalline substrate comprises lithium tantalate.

32. A crystalline substrate based device according to claim 1 and wherein said microstructure comprises a surface acoustic wave device.

33. A chip scale packaged crystalline substrate according to claim 1 and wherein said microstructure comprises a surface acoustic wave device.

34. A method of produce a crystalline substrate based device according to claim 21 and wherein said crystalline substrate comprises lithium tantalate.

35. A method of produce a crystalline substrate based device according to claim 21 and wherein said microstructure comprises a surface acoustic wave device.

For the Applicant,

Sanford T. Colb & Co.
C: 35699

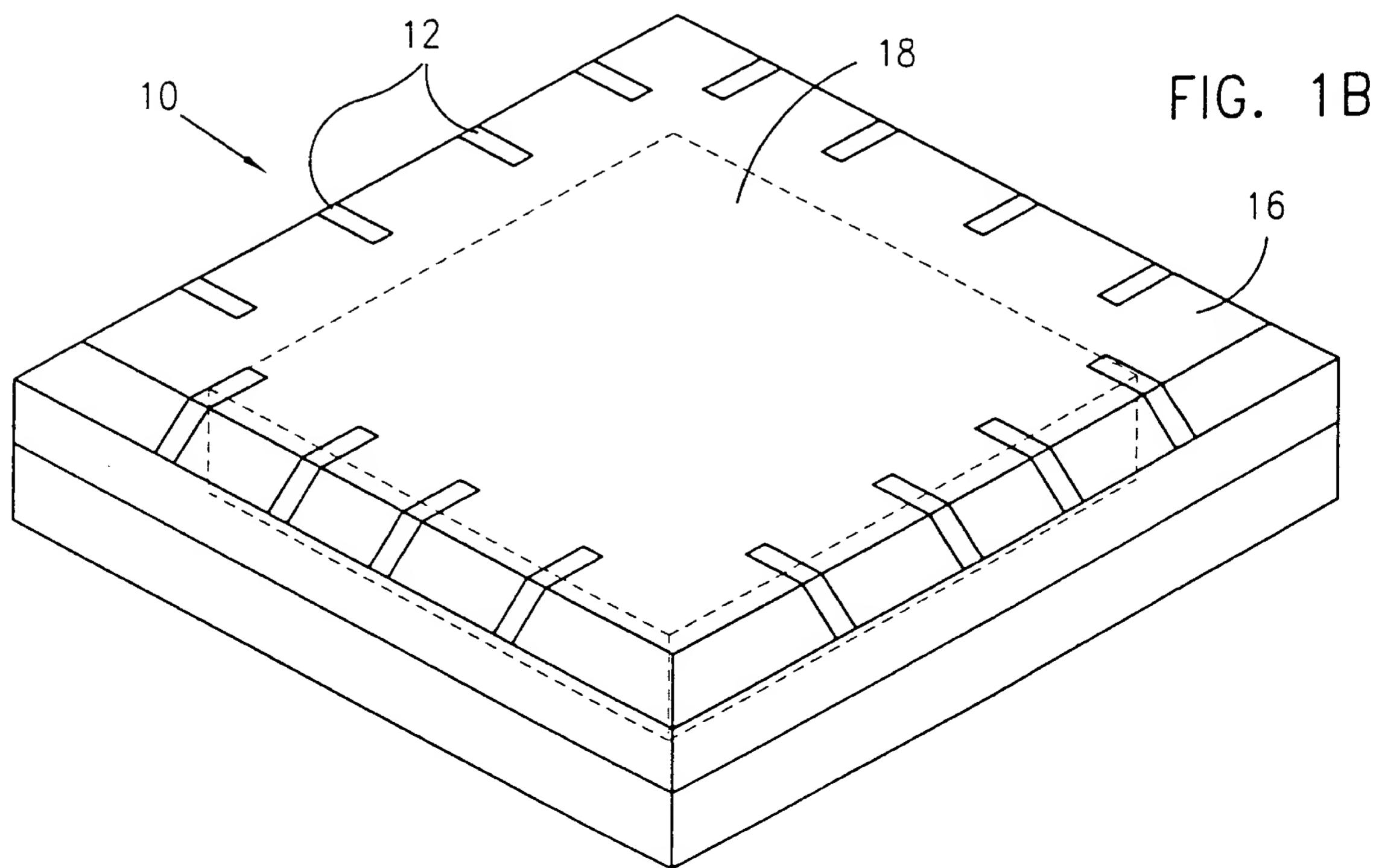
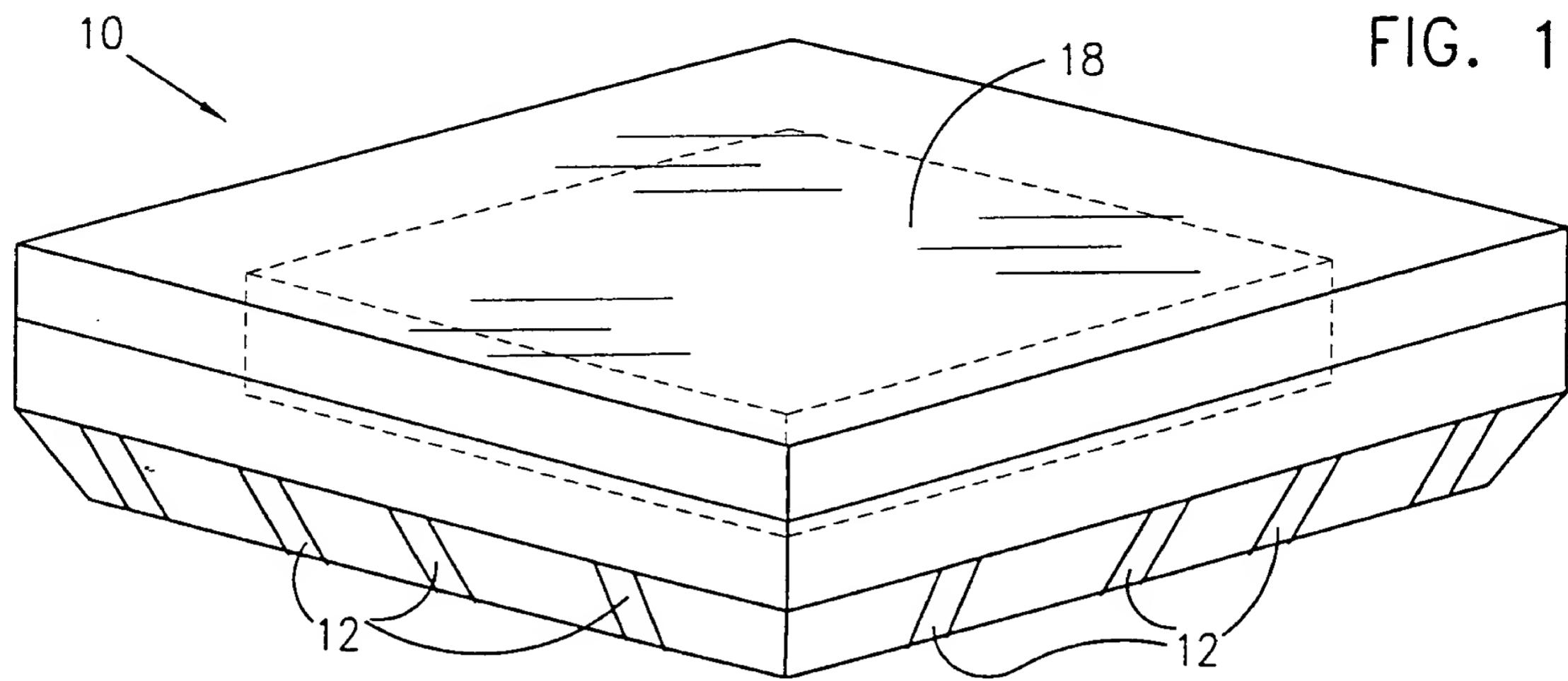


FIG. 2A

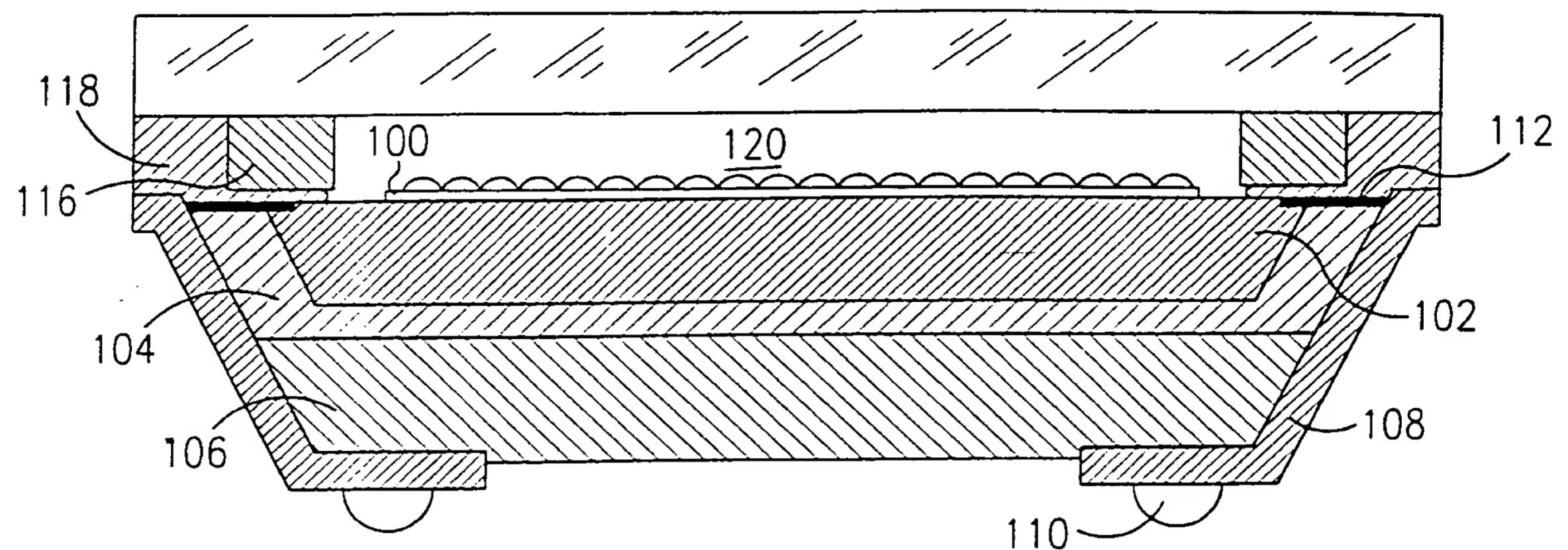


FIG. 2B

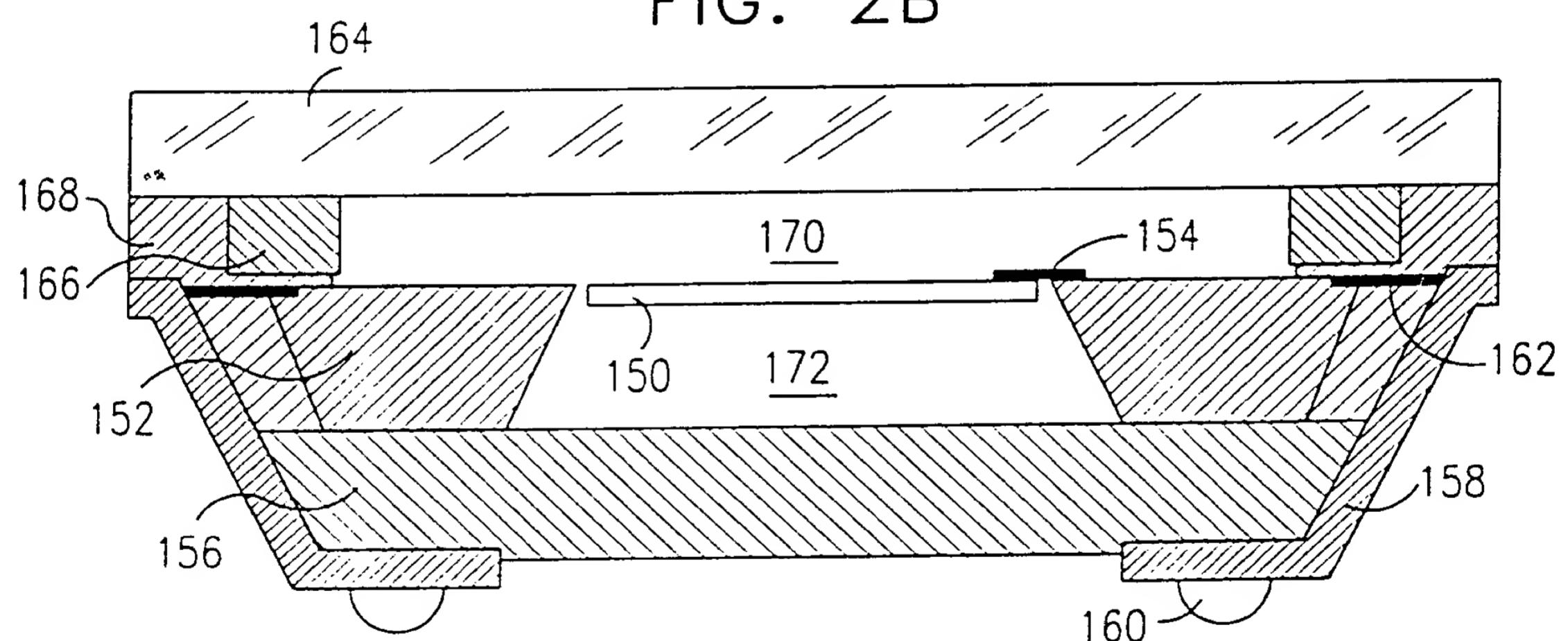
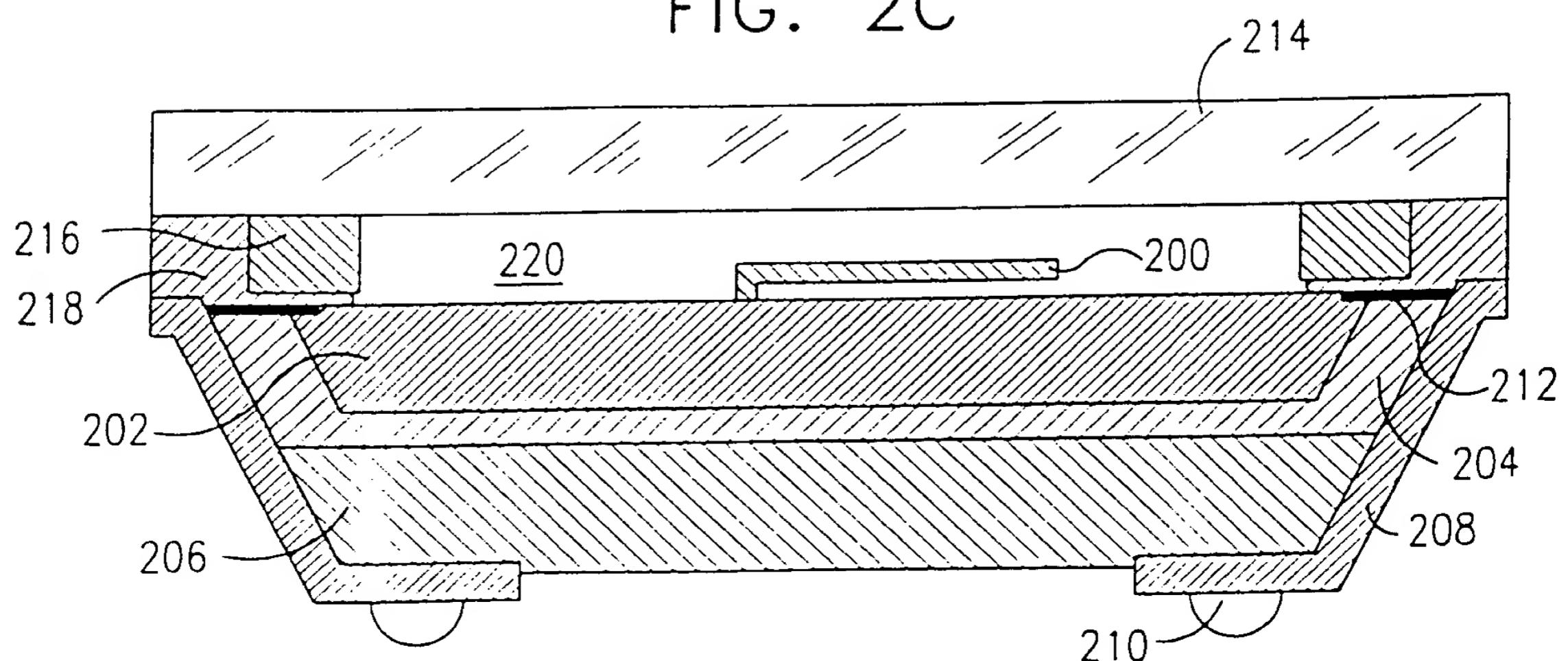


FIG. 2C



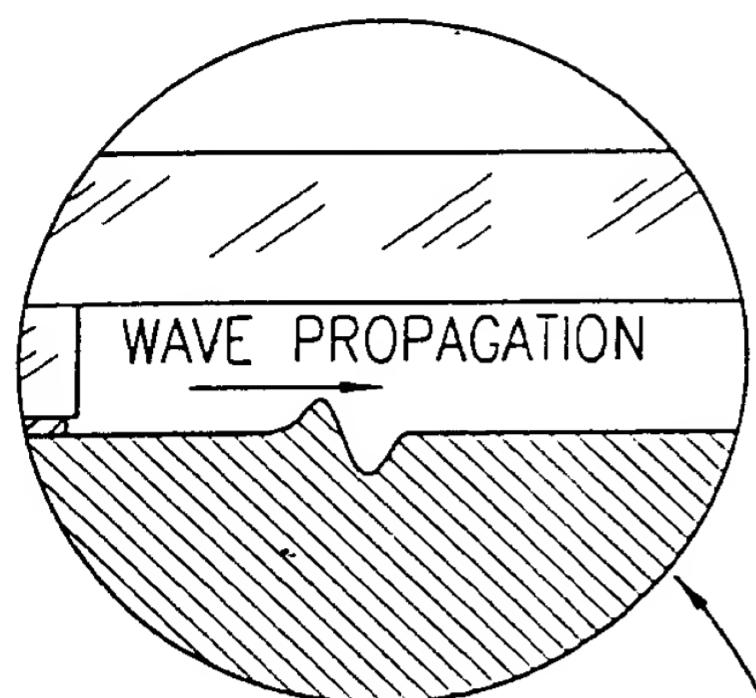


FIG. 2D

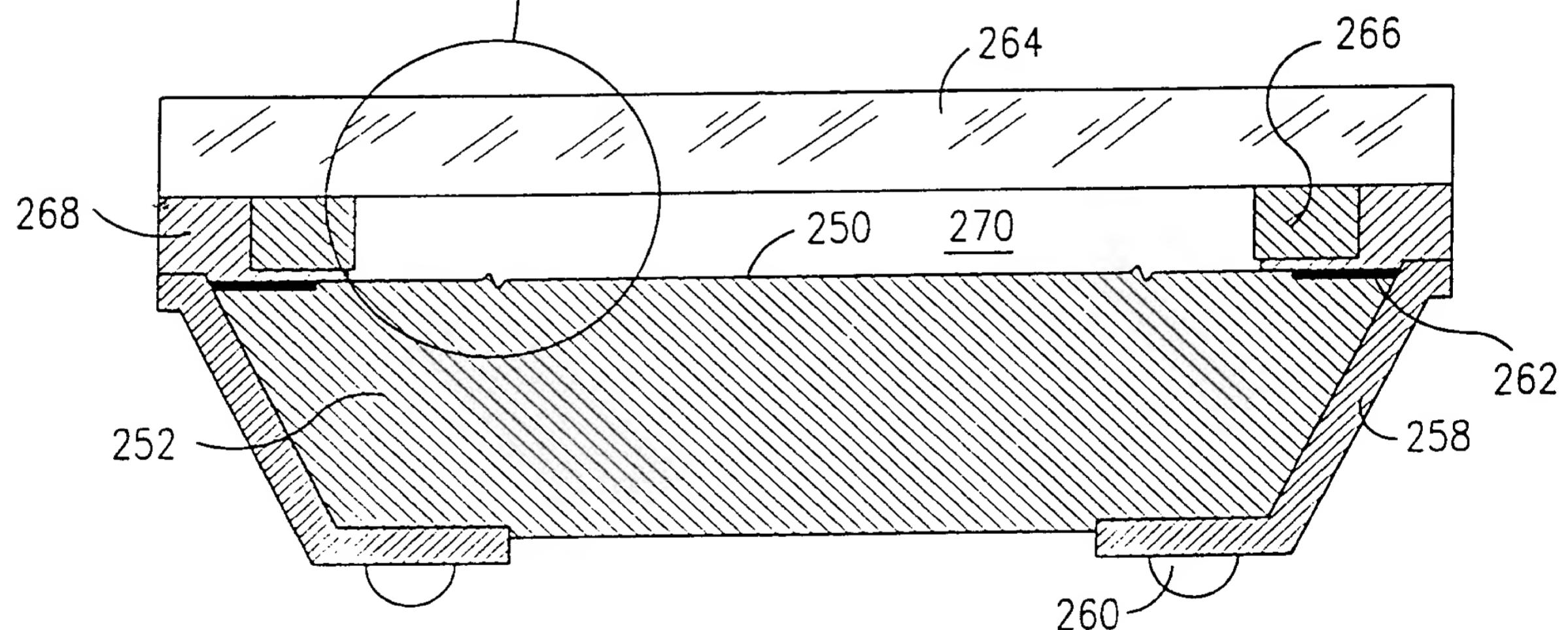


FIG. 3

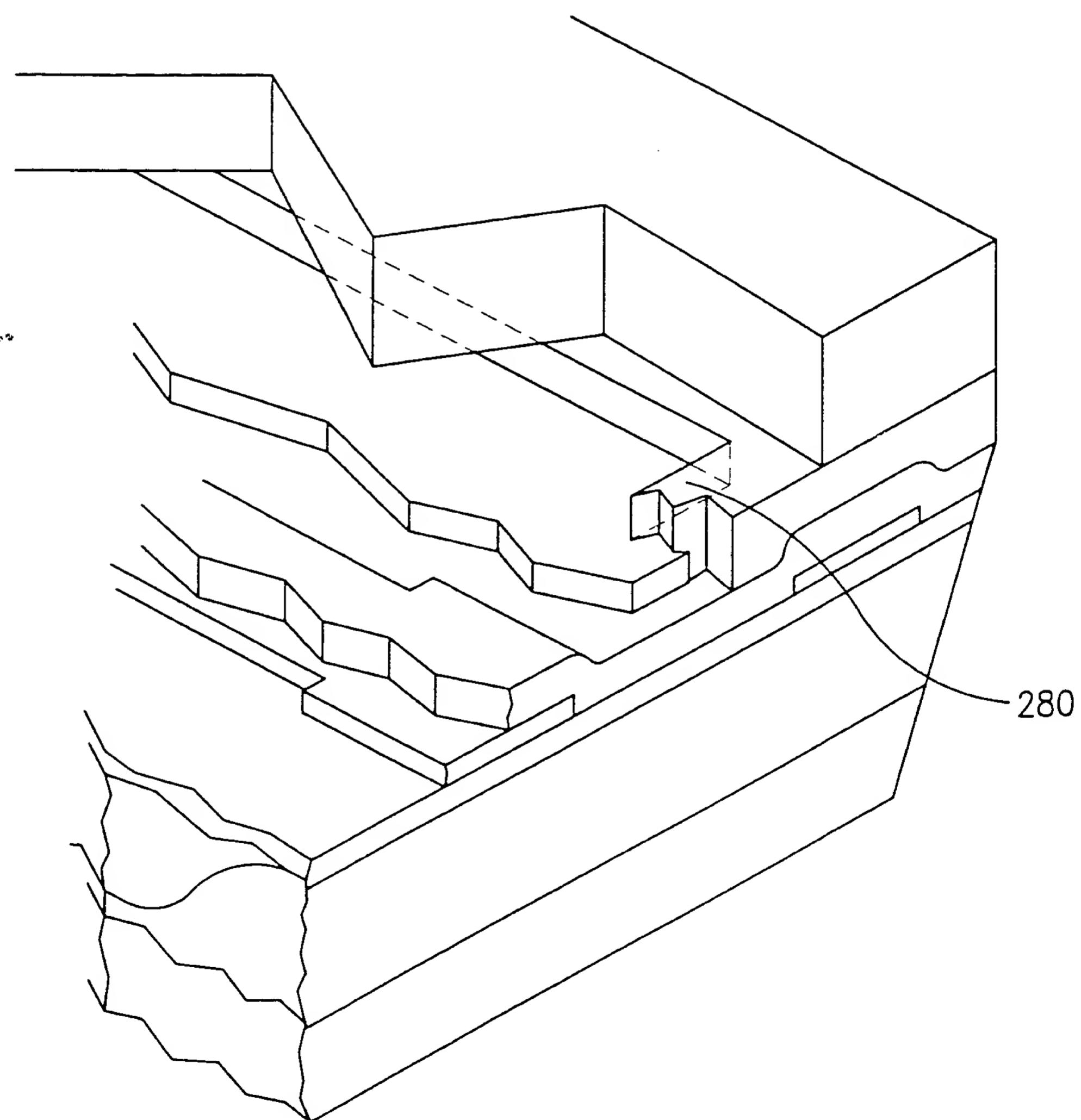


FIG. 4A

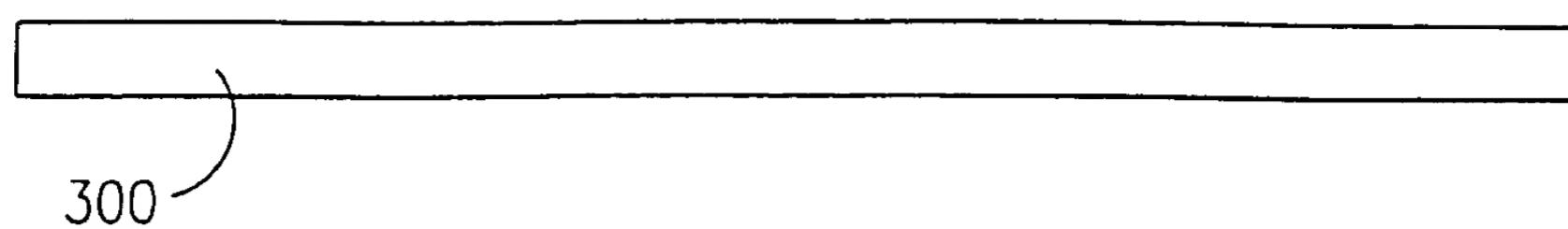


FIG. 4B

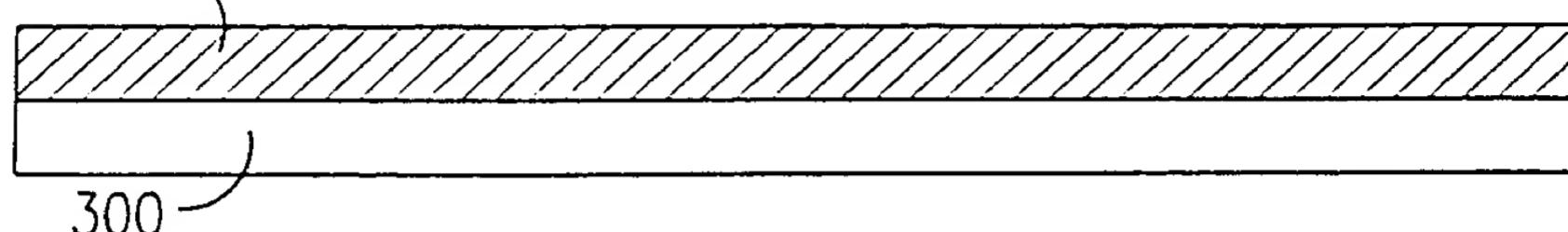


FIG. 4C

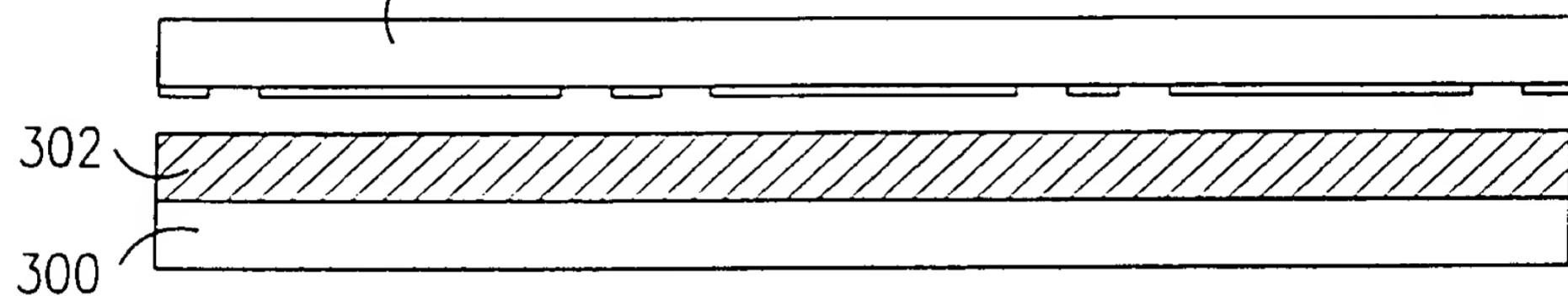


FIG. 4D

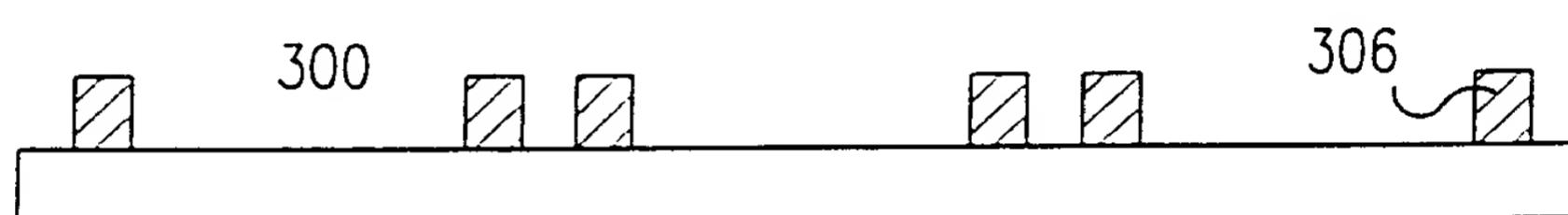


FIG. 4E

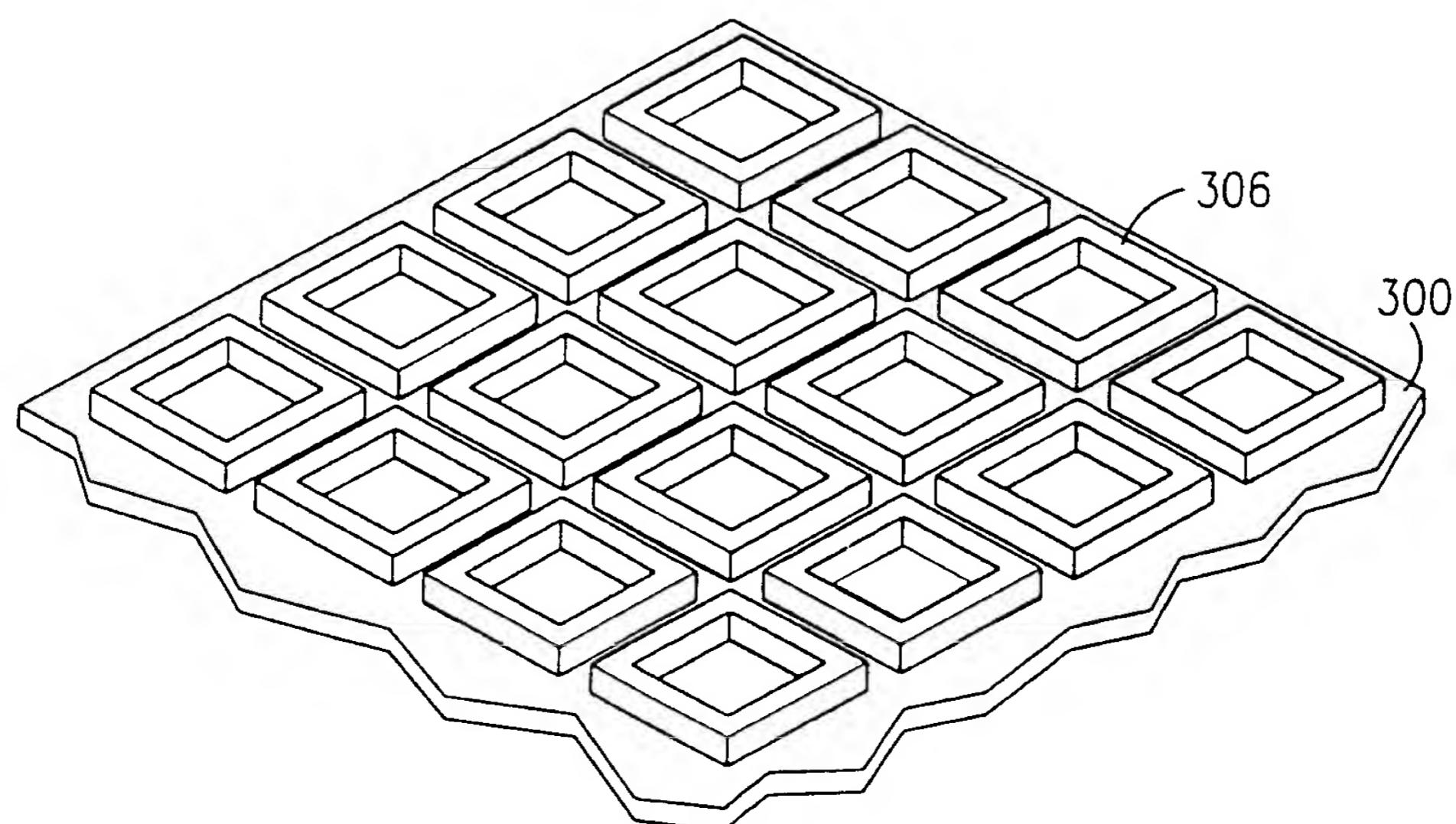


FIG. 5A

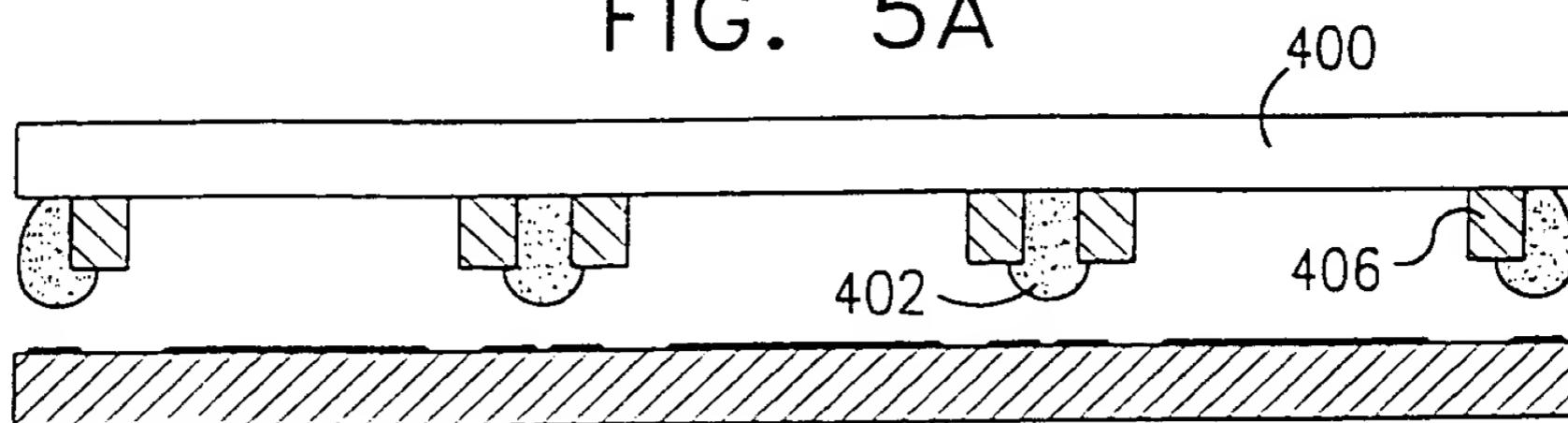


FIG. 5B

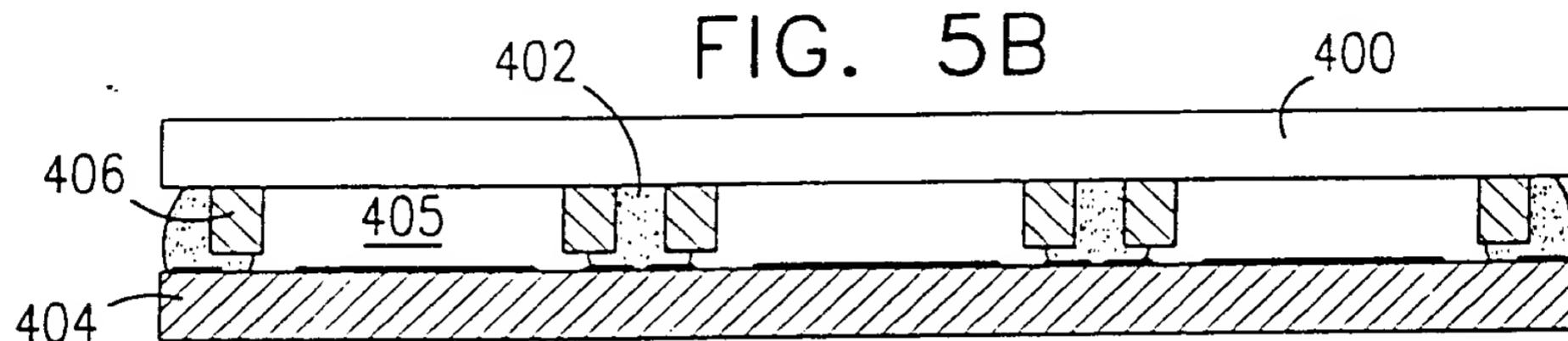


FIG. 5C

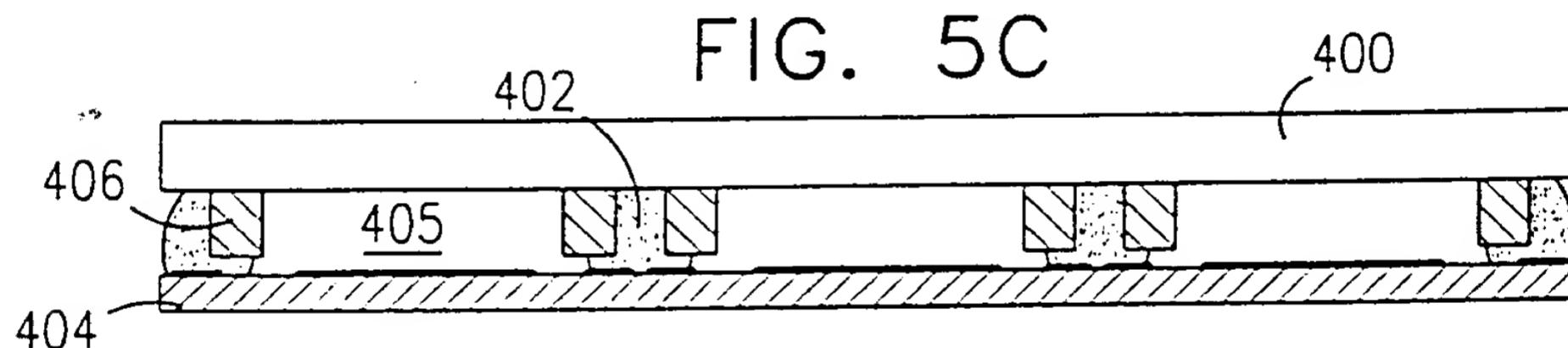


FIG. 5D

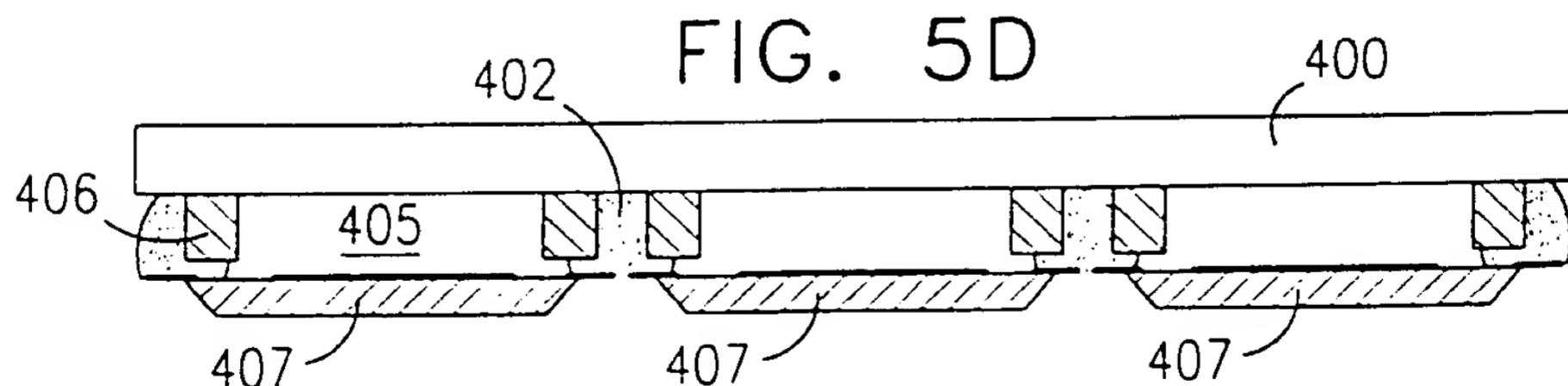
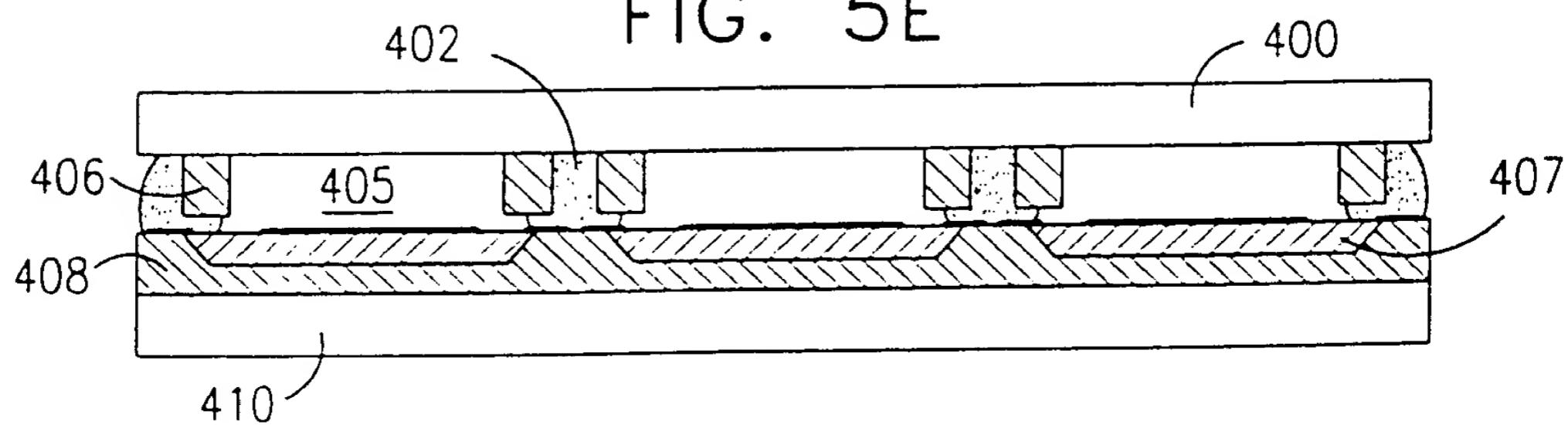


FIG. 5E



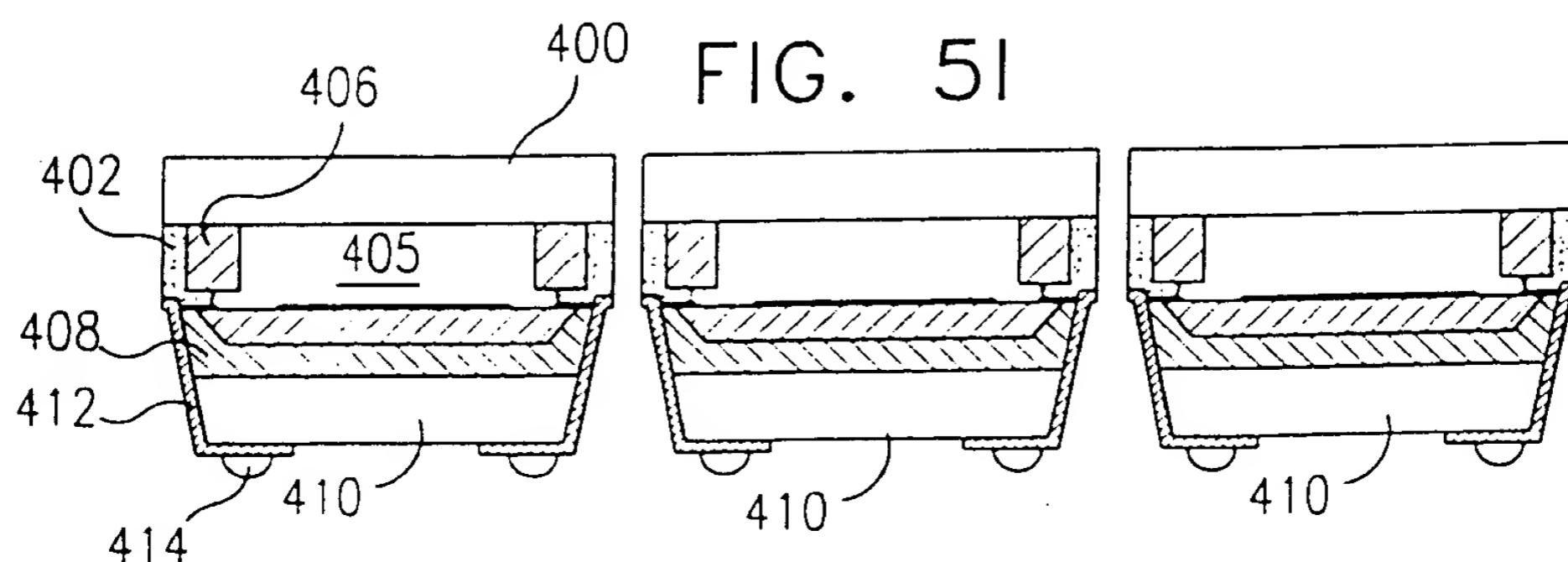
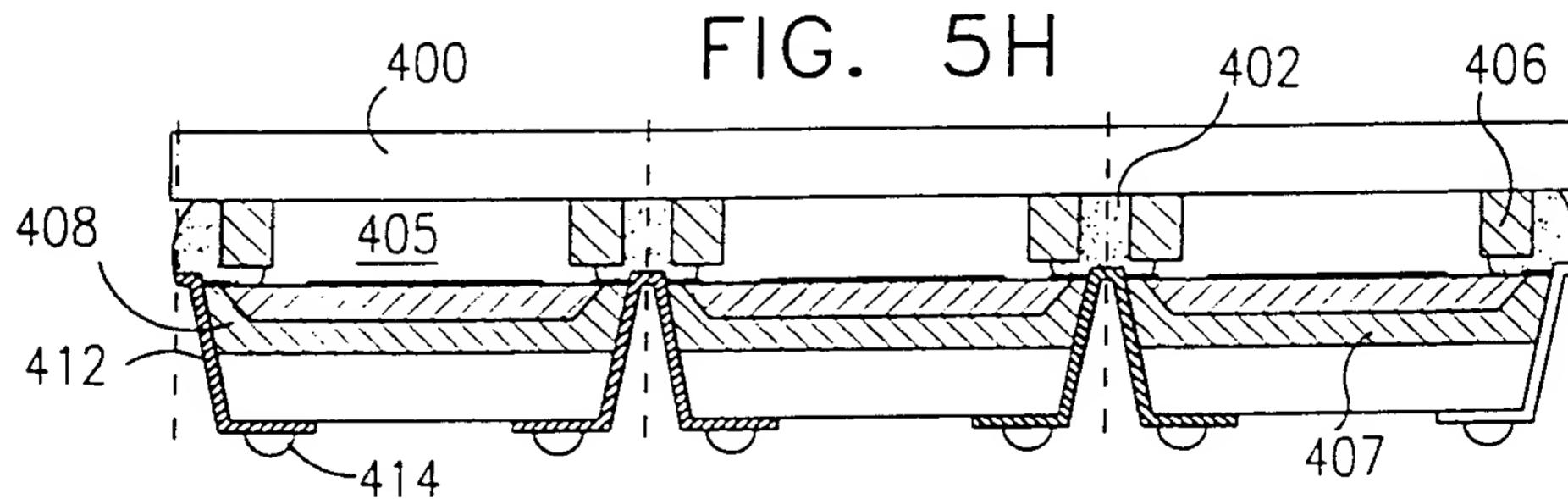
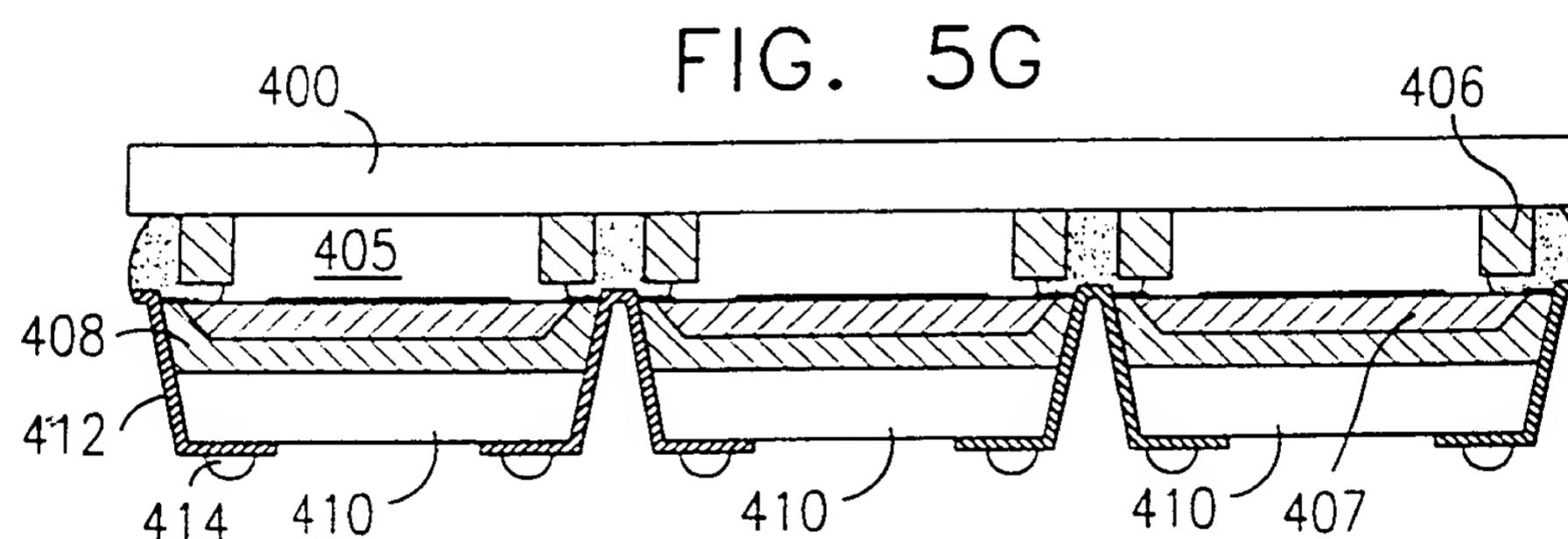
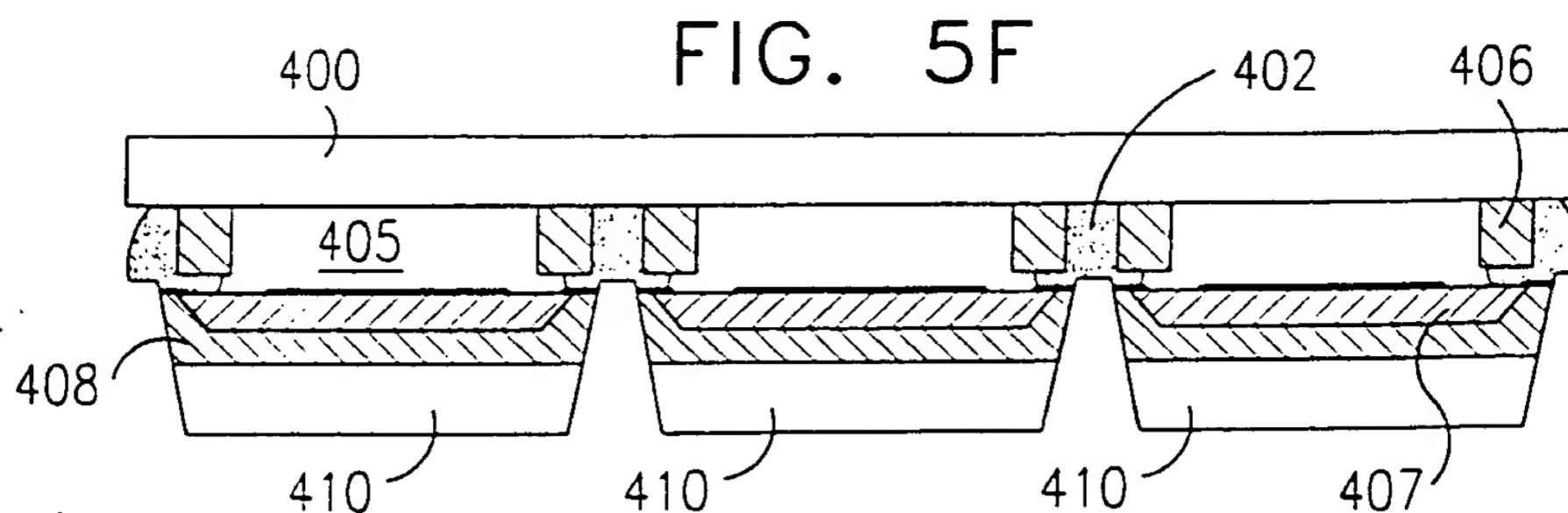


FIG. 6A

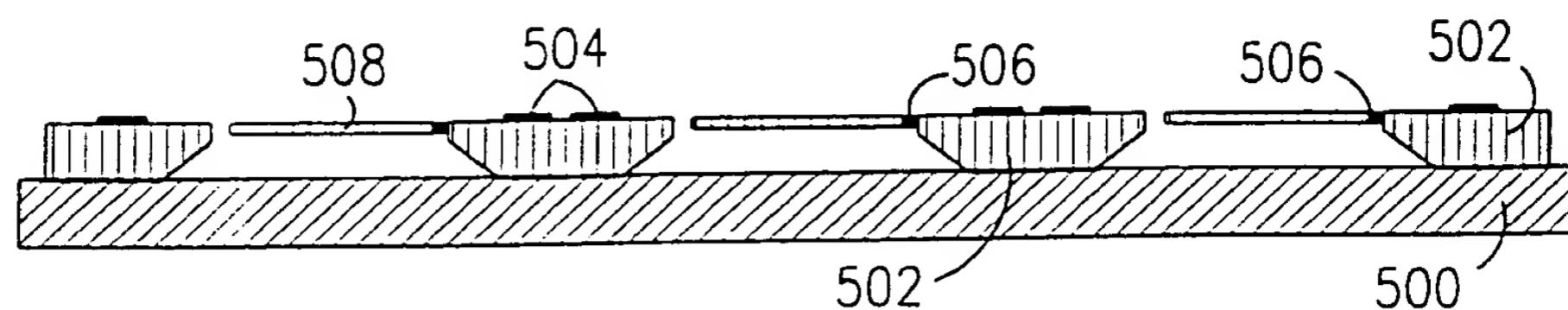


FIG. 6B

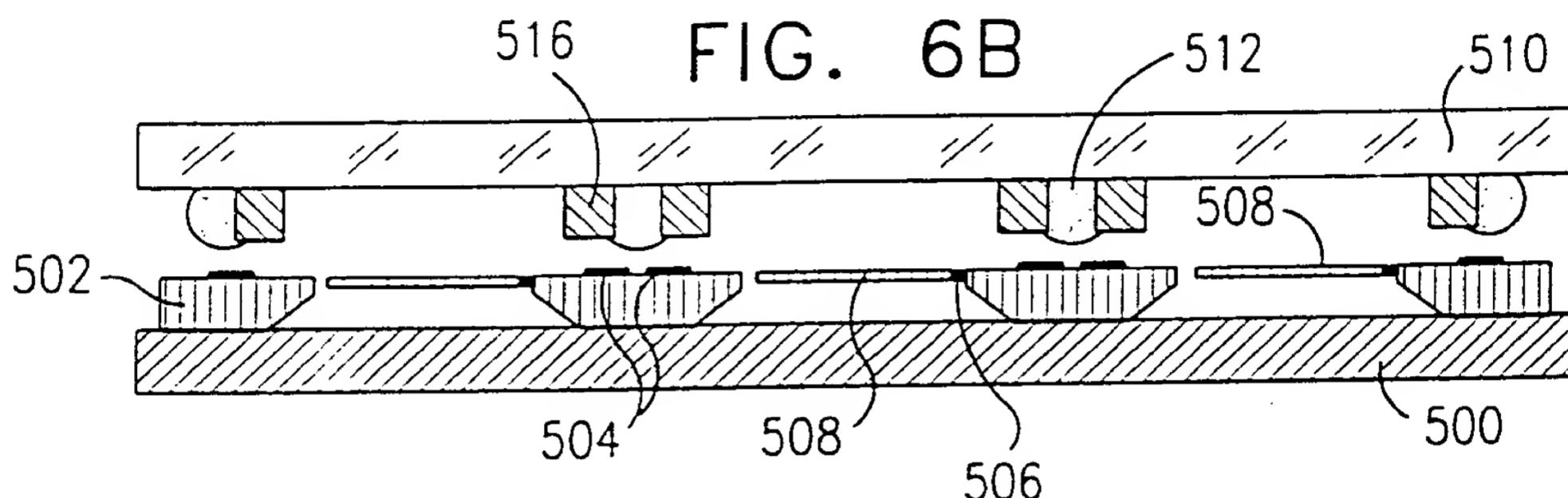


FIG. 6C

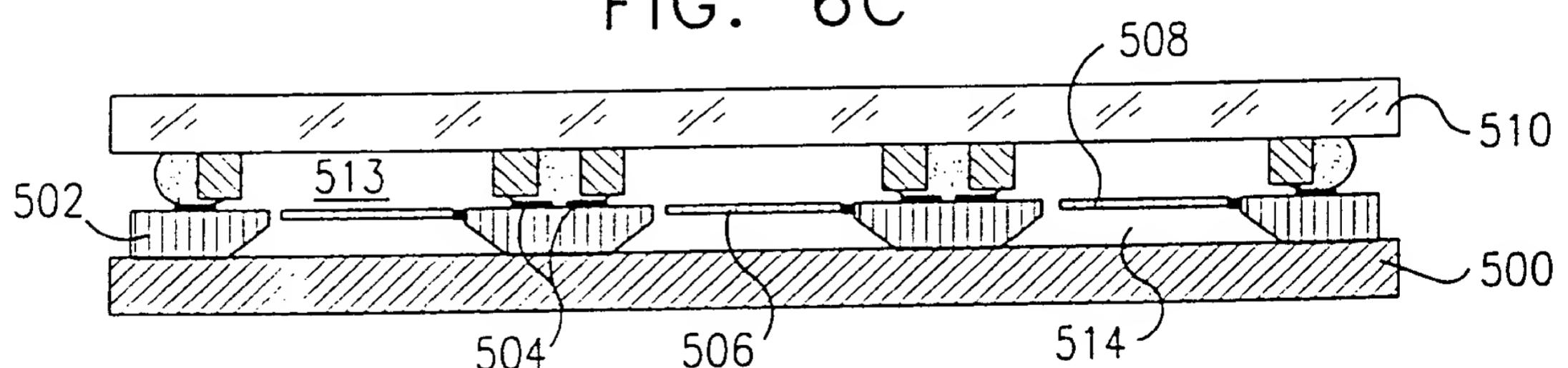


FIG. 6D

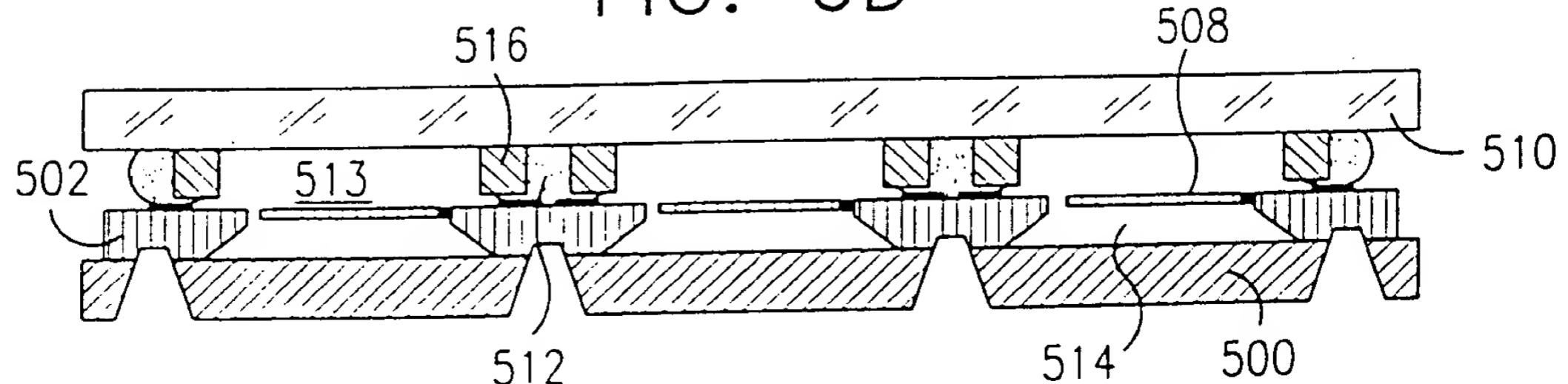


FIG. 6E

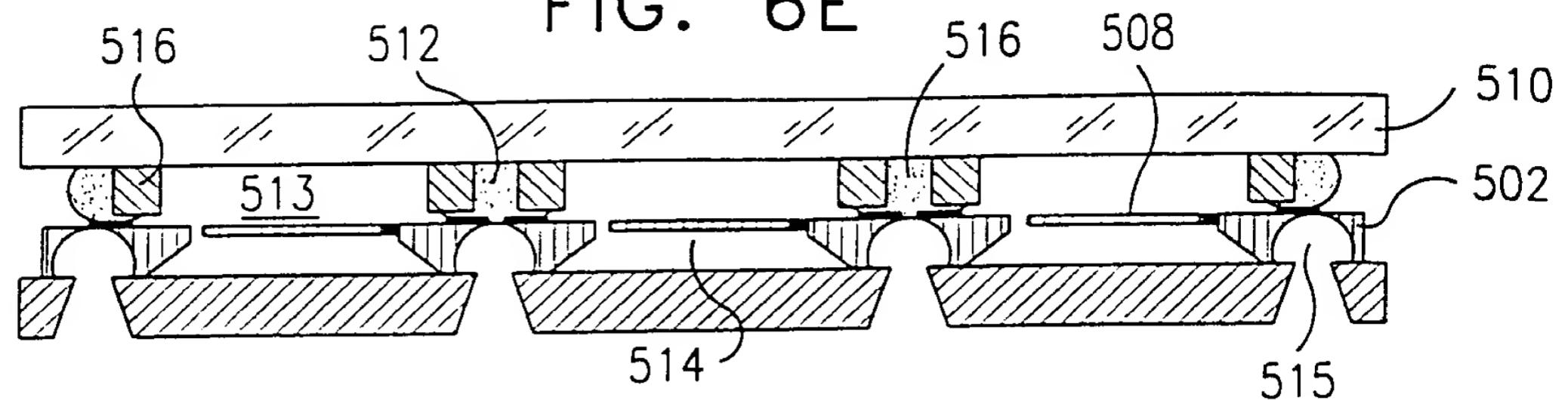


FIG. 6F

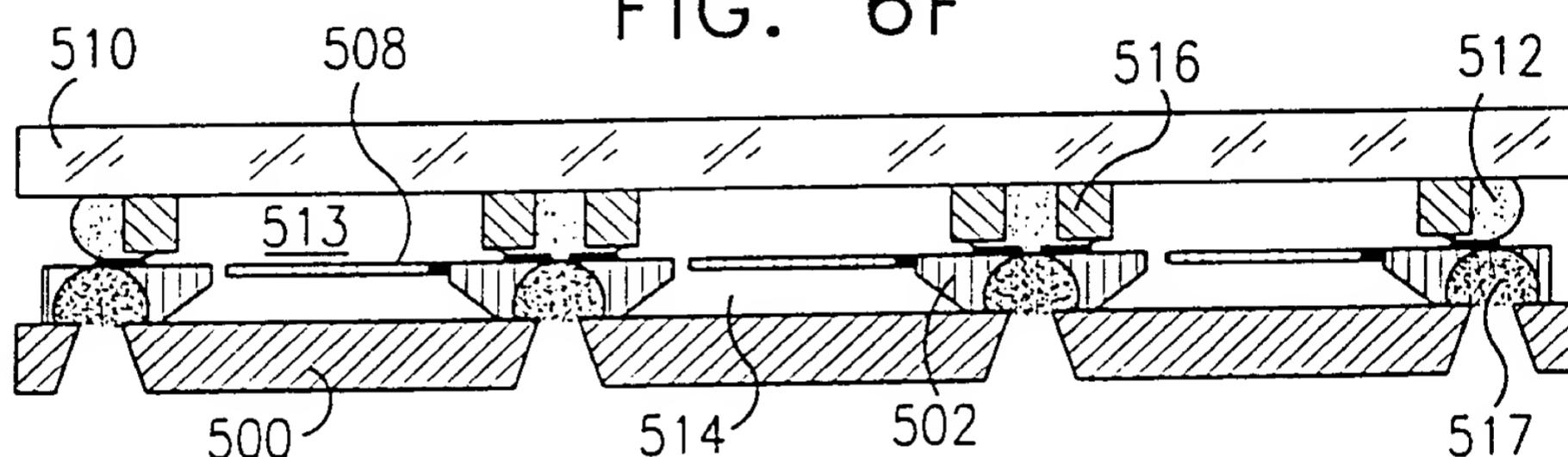


FIG. 6G

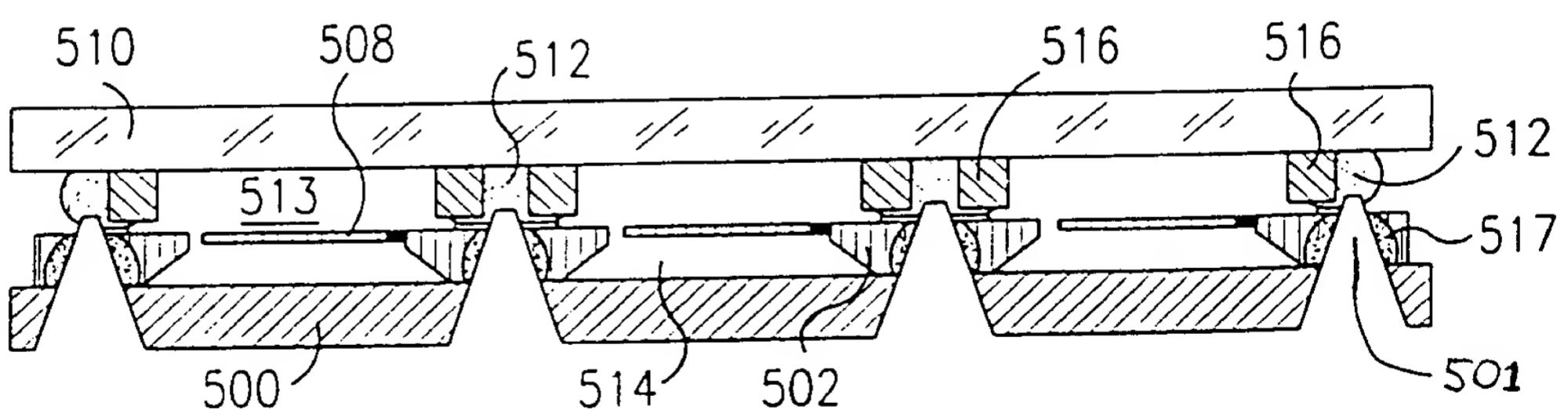
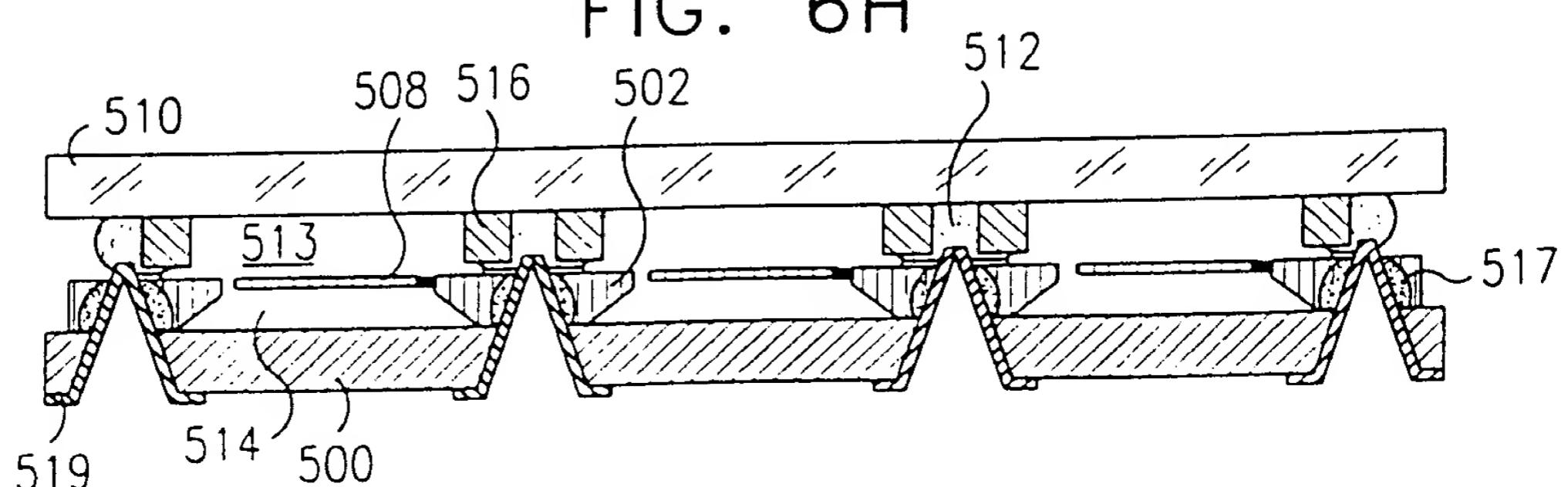


FIG. 6H



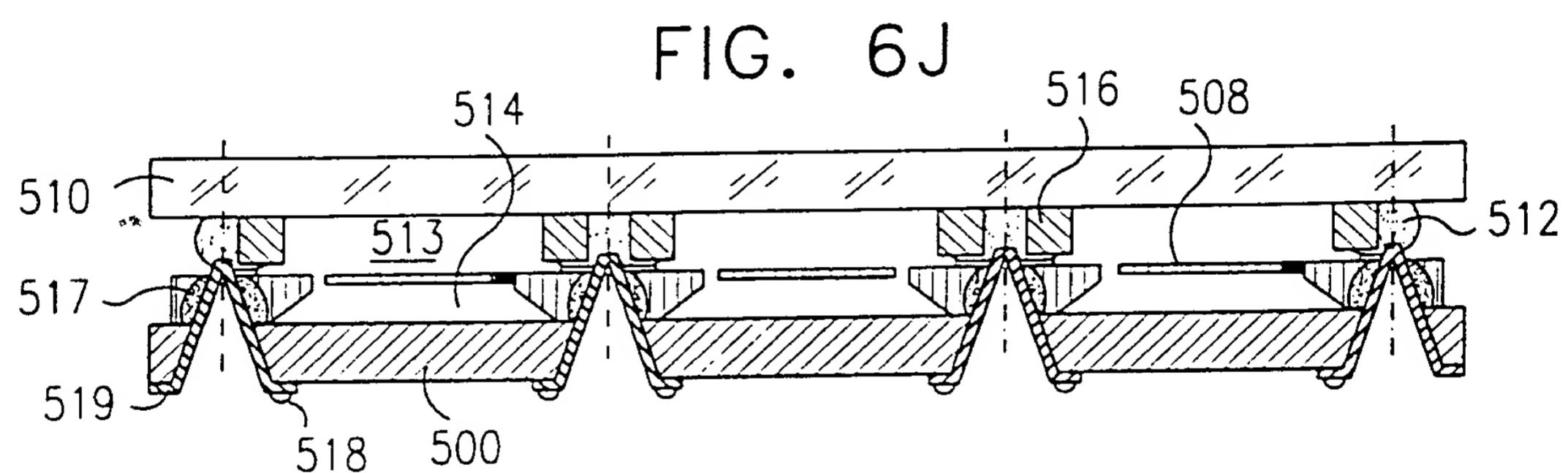
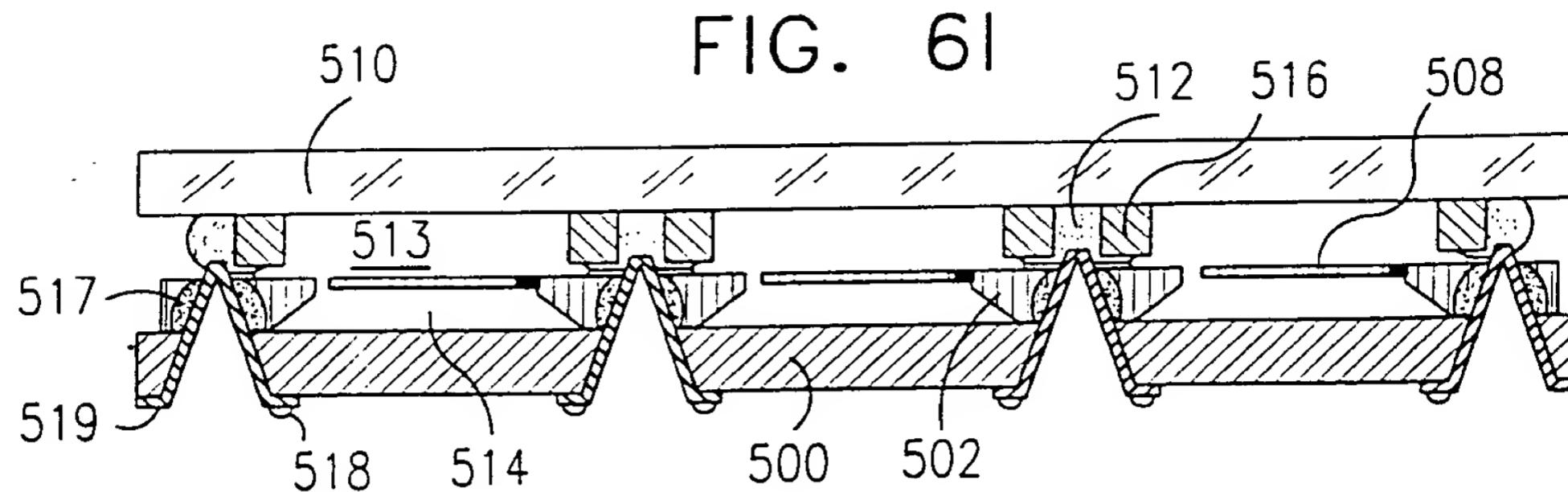


FIG. 6K

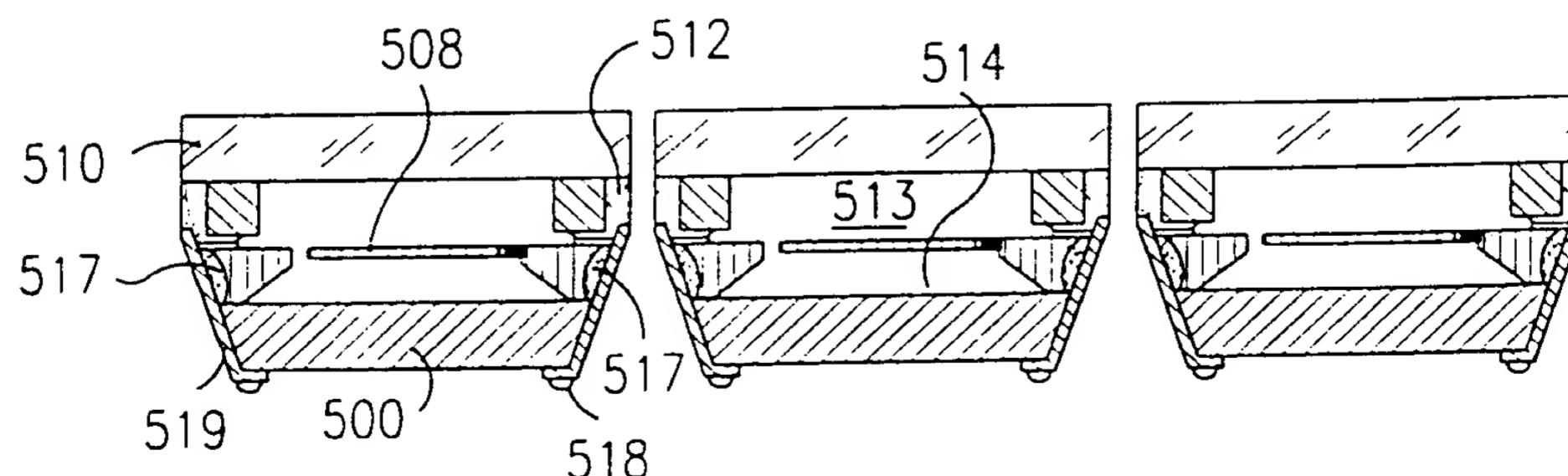


FIG. 7A

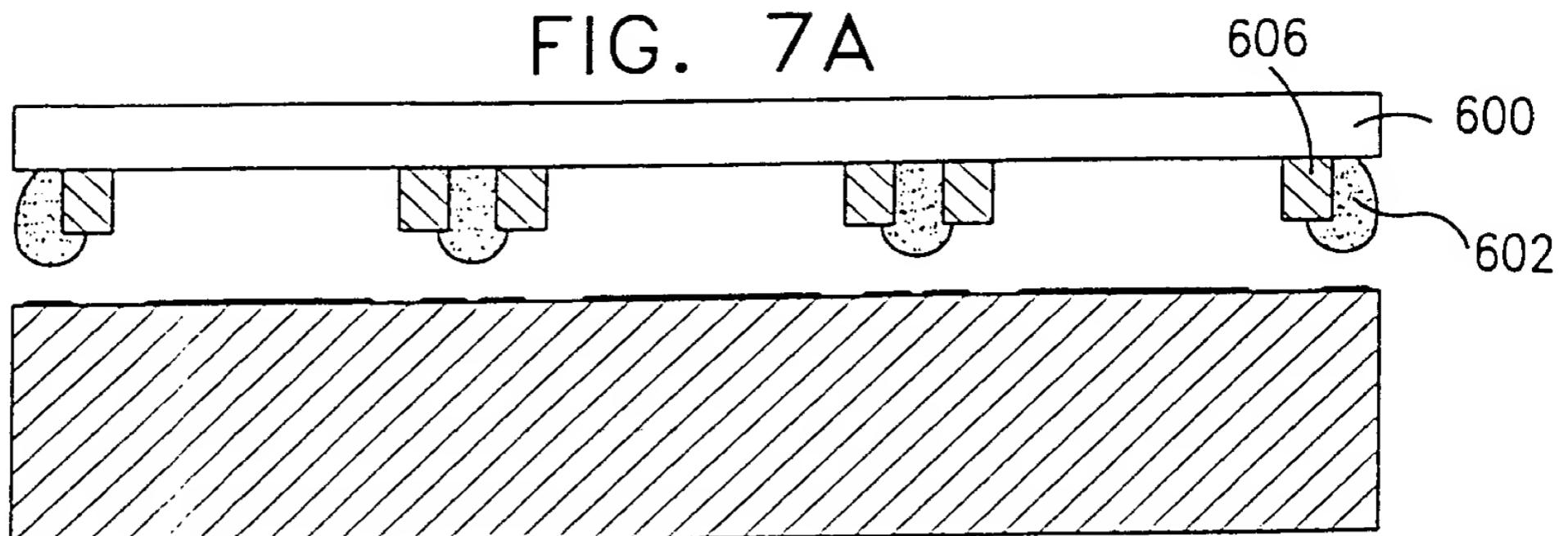


FIG. 7B

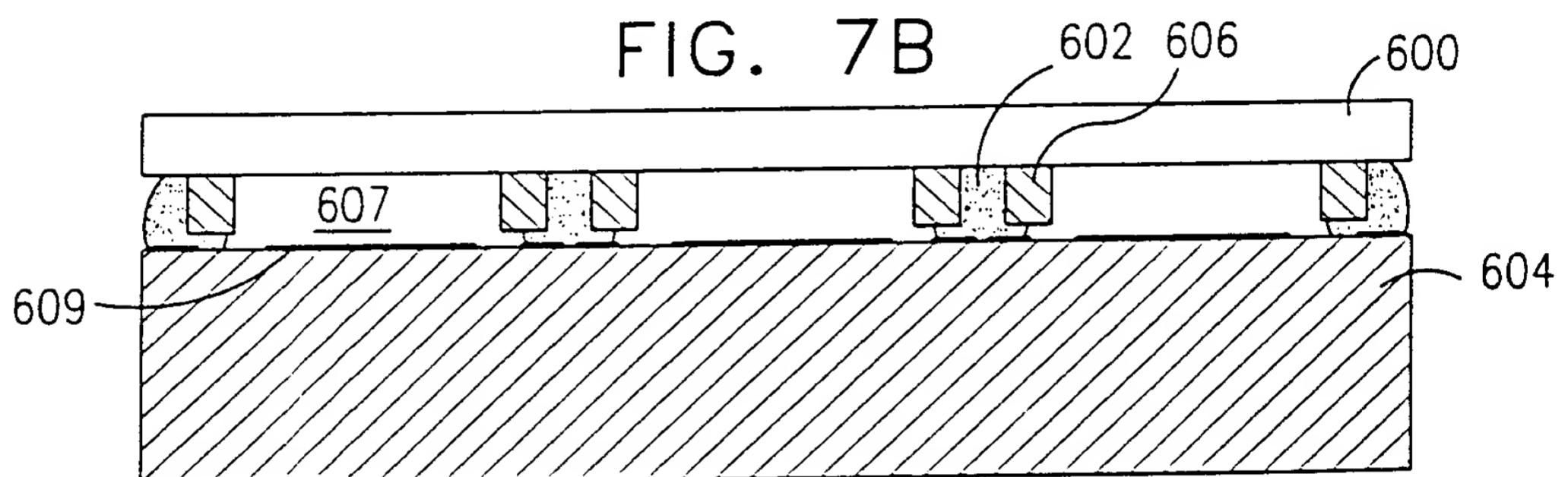


FIG. 7C

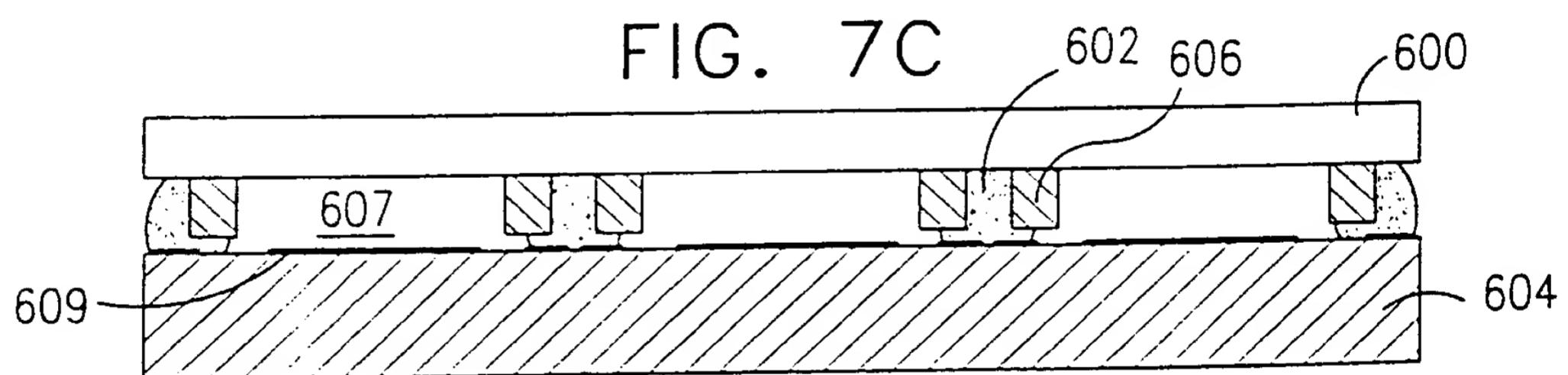


FIG. 7D

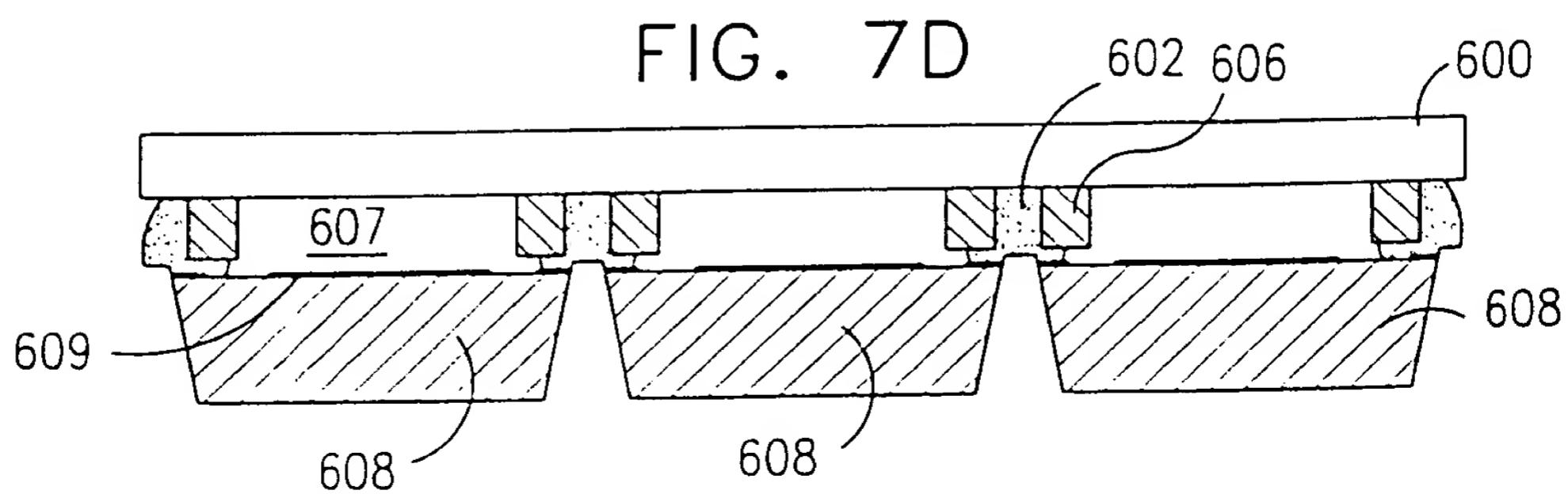


FIG. 7E

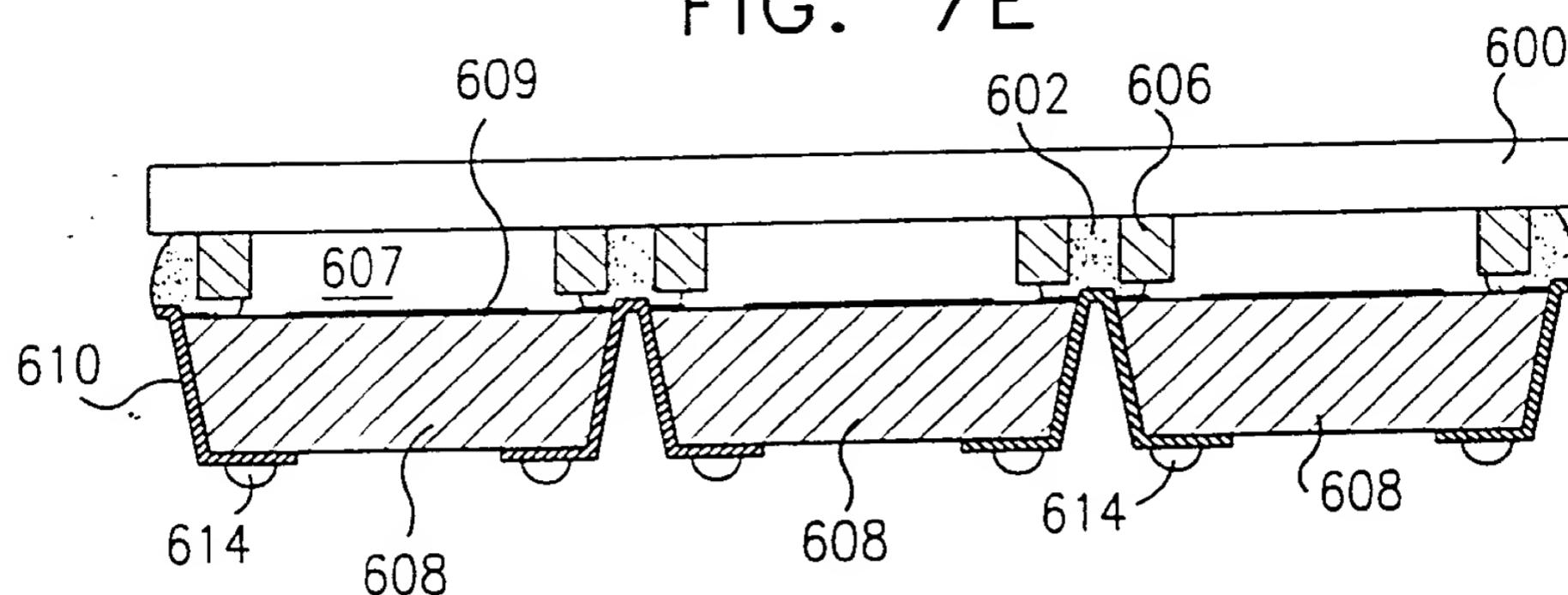


FIG. 7F

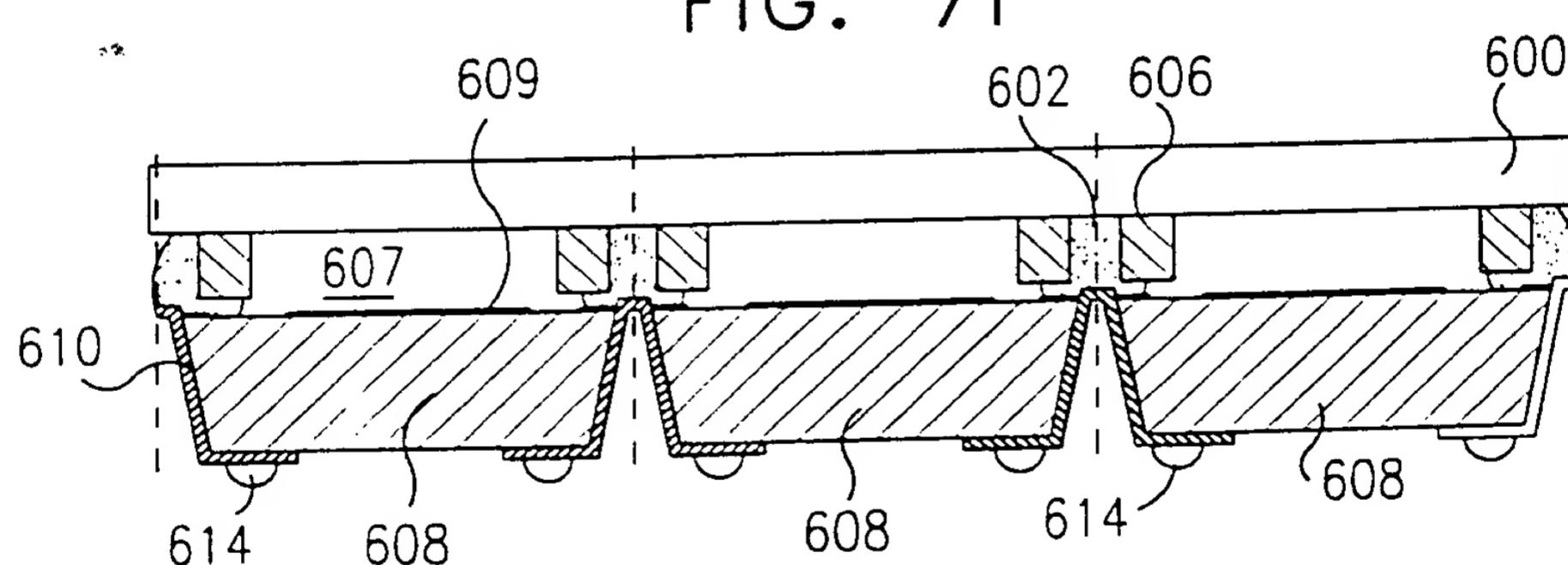


FIG. 7G

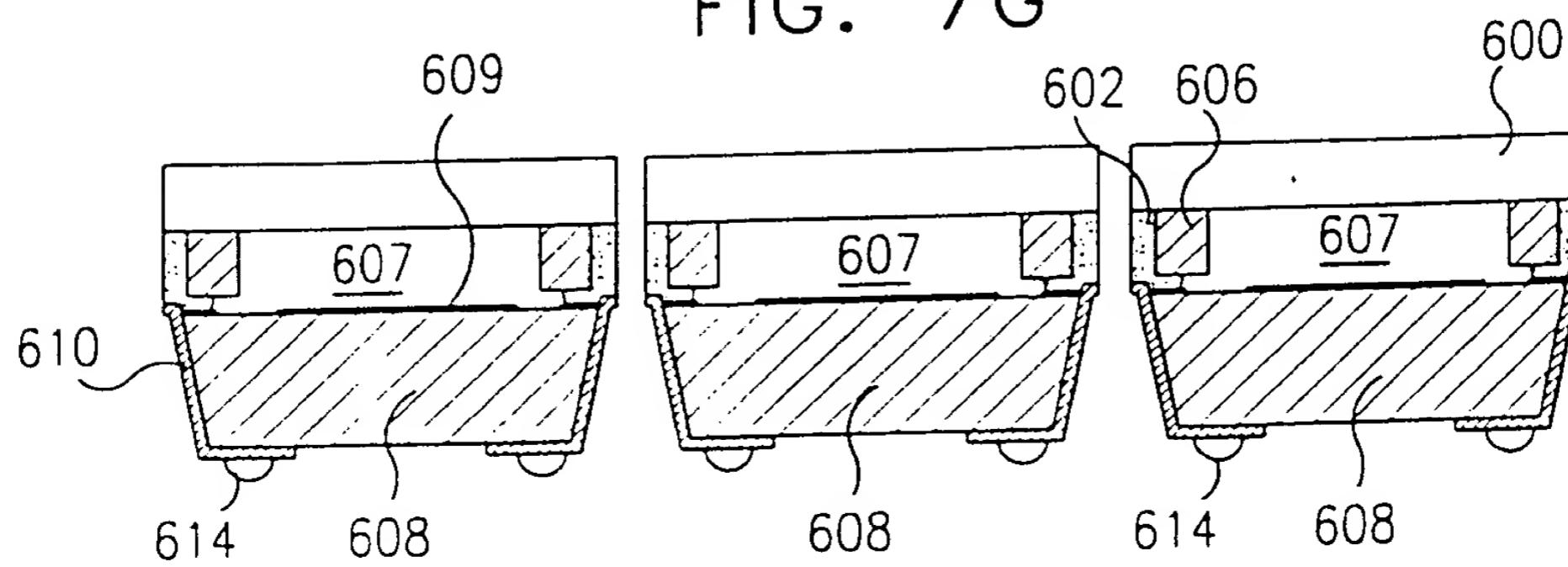
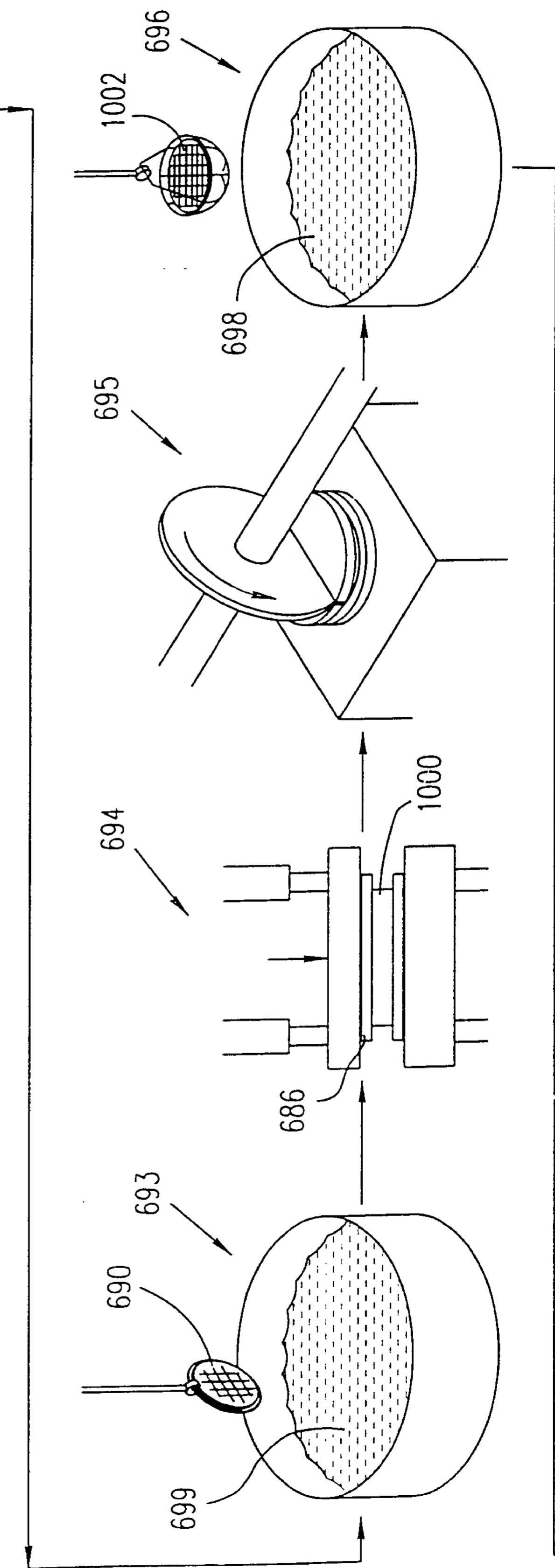
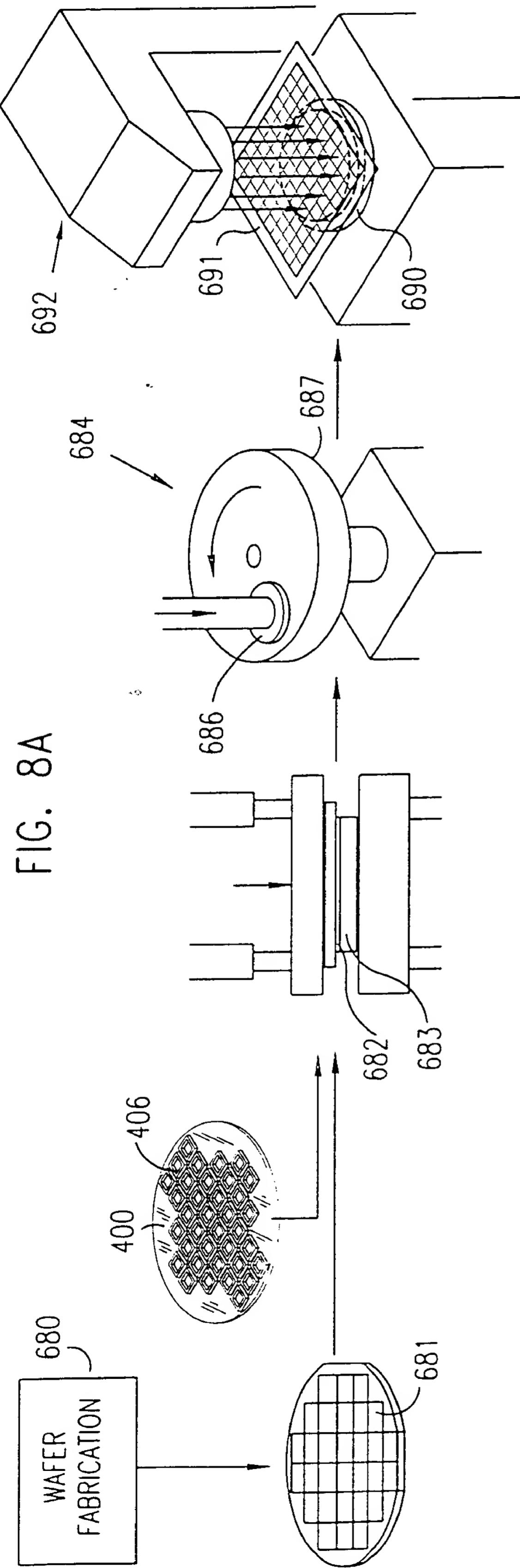


FIG. 8A



A

FIG. 8B

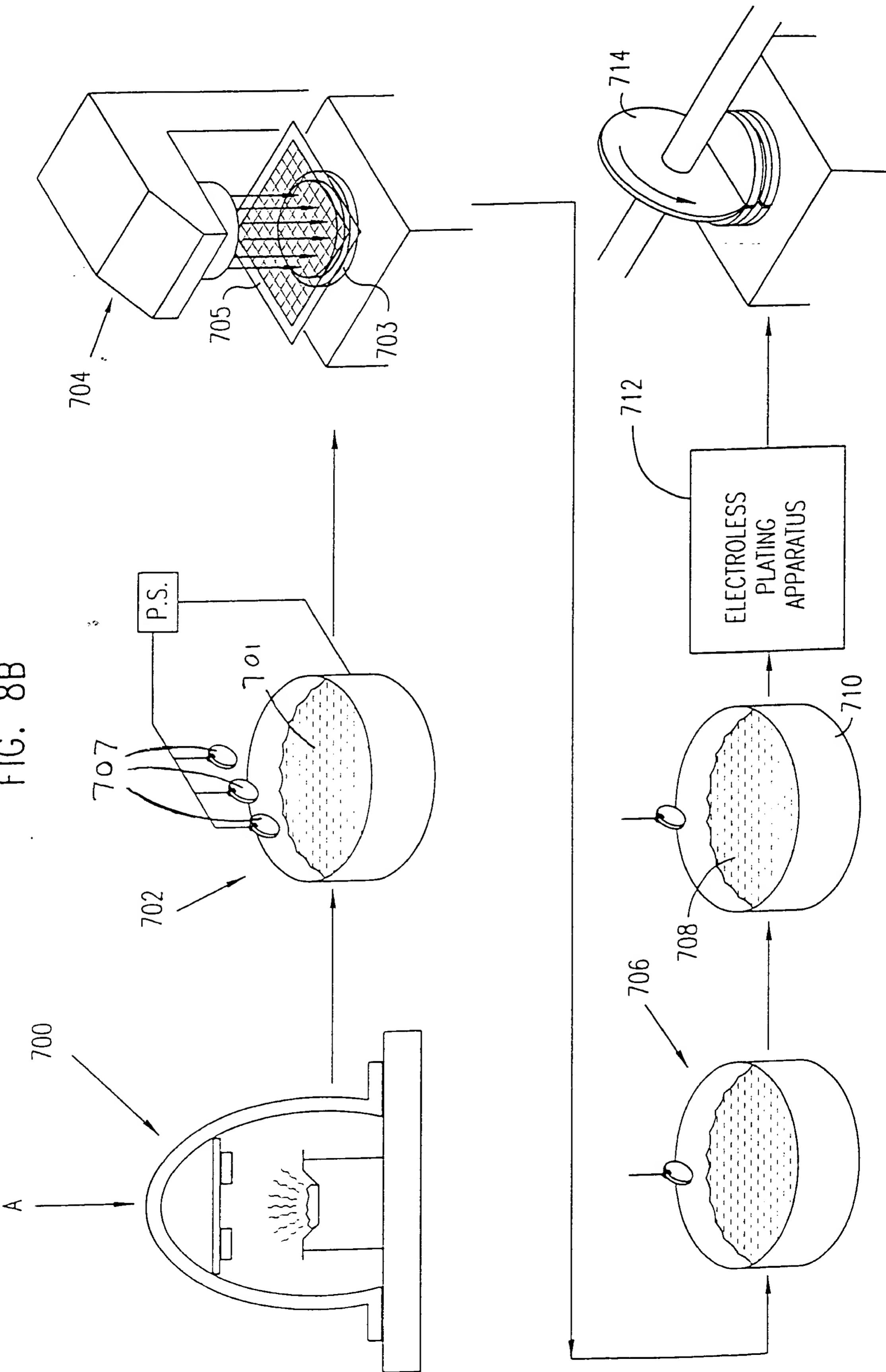
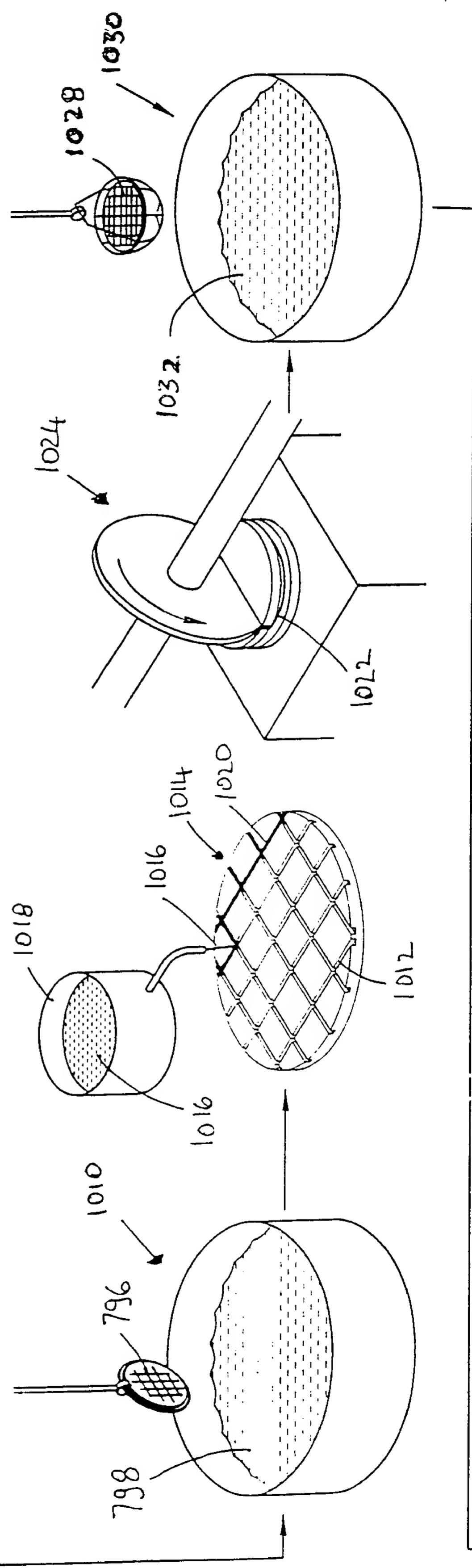
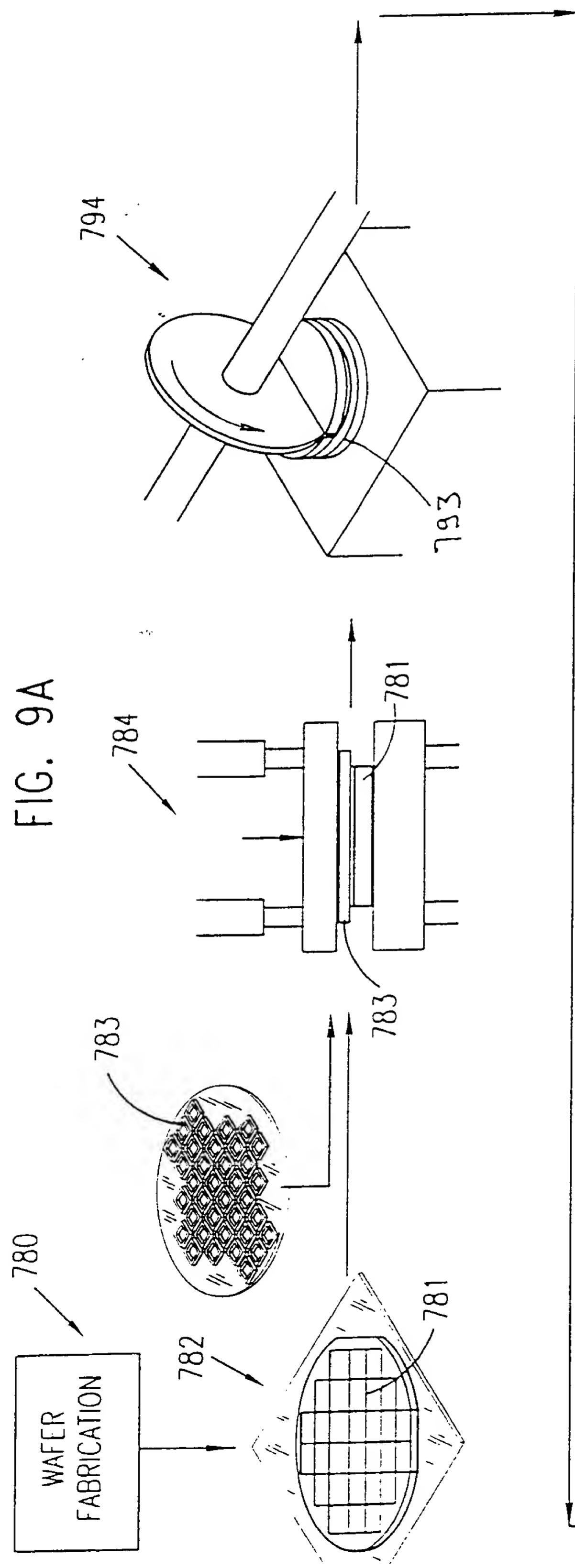
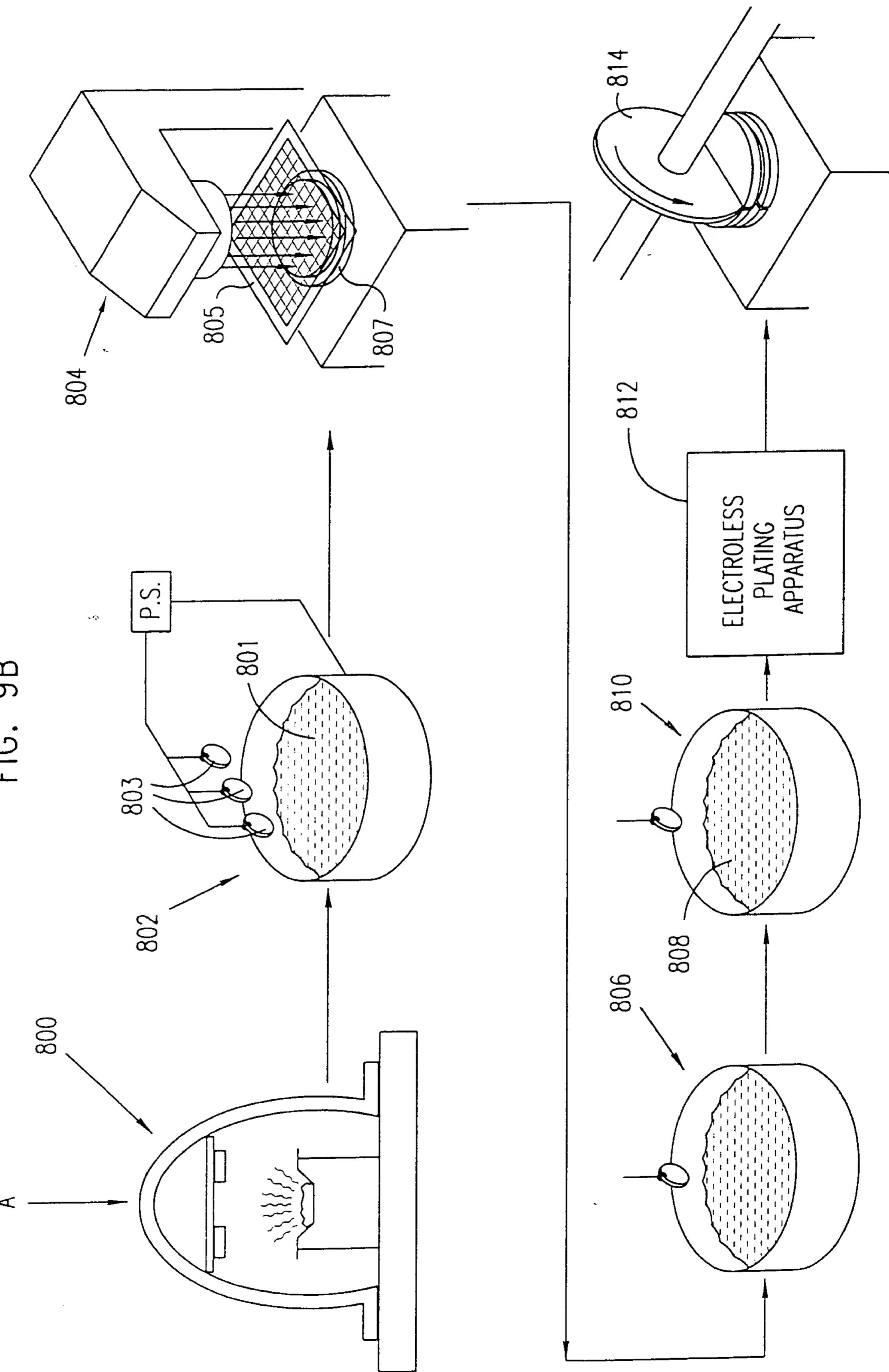


FIG. 9A



A

FIG. 9B



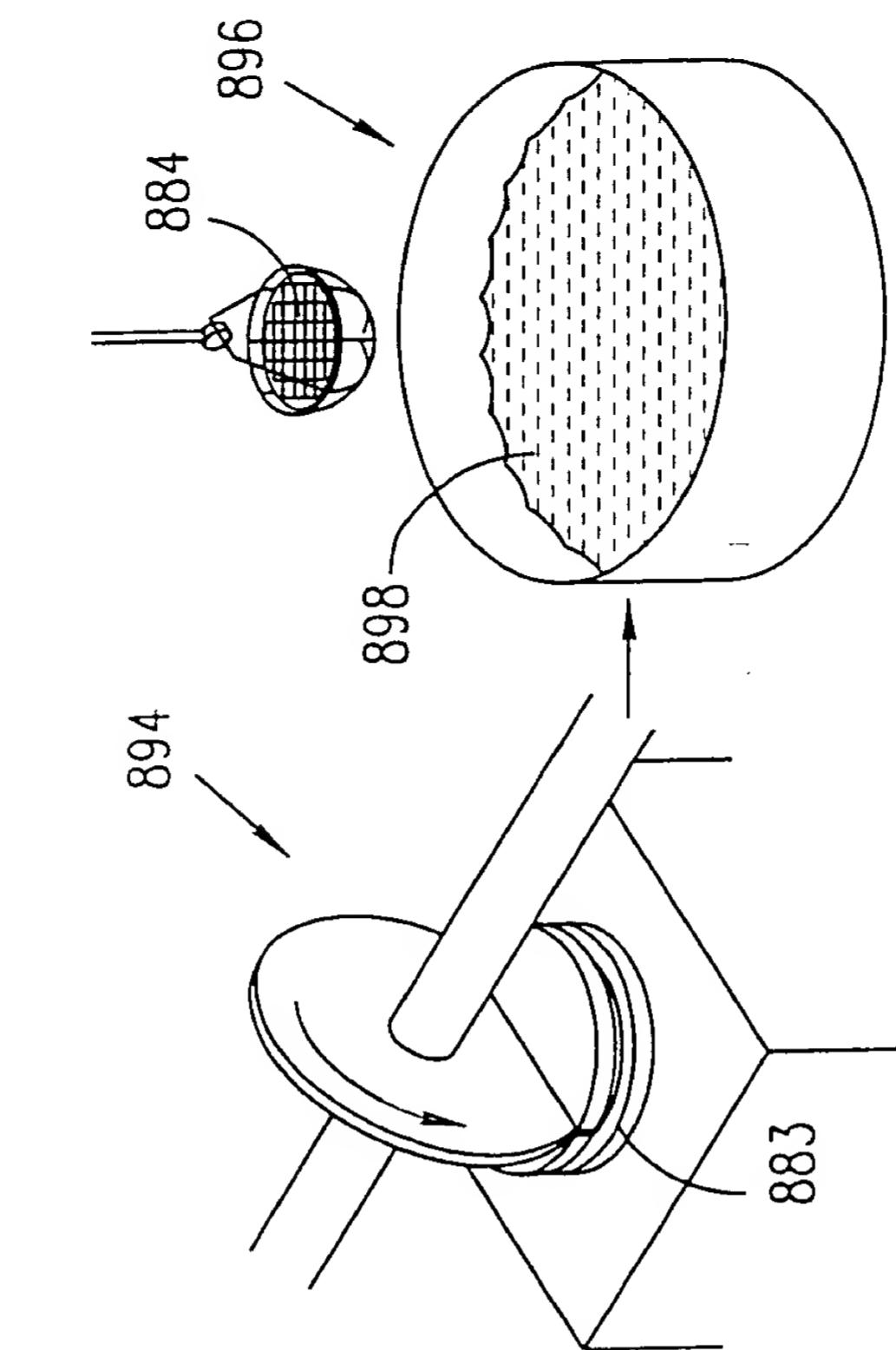


FIG. 10A

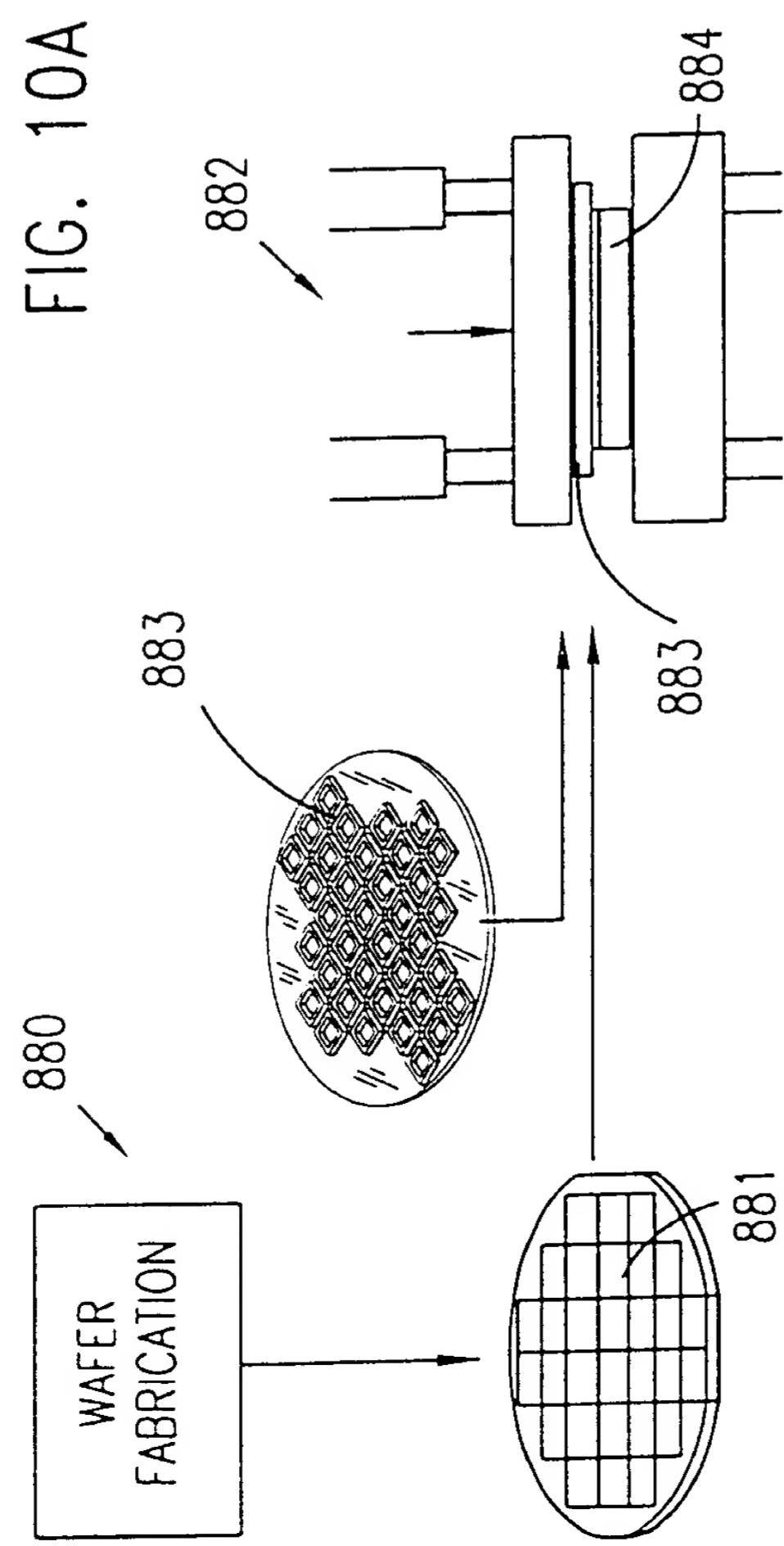


FIG. 10B

